

TMP04CH01FXXX(JTMP04CH01XXXS)

CMOS 4BIT LL MICROCONTROLLER

(LL : LOW POWER CONSUMPTION &

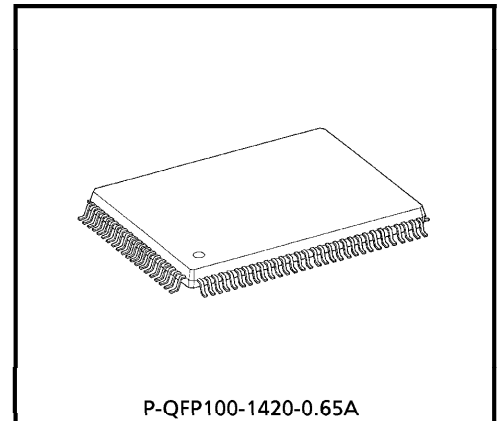
VOLTAGE OPERATION MICROCONTROLLER)

◆OUTLINE

The TMP04CH01FXXX is a high-performance microcontroller designed to be in a variety of low-voltage products.

It is a 4bit CMOS LL microcontroller with integrated a 4bit high-performance CPU, memory (static work RAM and program ROM). LCD display LL controller driver, and a multi-function timer into a single chip.

The basic features are as follows.



Weight : 1.65g (Typ.)

◆FEATURES

- Number of instructions : 56
- Minimum instruction execution time : $61\mu s$ (at 32.768kHz)
 $1\mu s$ (at 2MHz / 3.0V)
- Oscillating circuit : Low-speed crystal oscillator (32.768kHz)
/ internal CR (33kHz at 1.5V)
High-speed crystal oscillator (2MHz at 3.0V)
/ external CR (200kHz at 1.5V)
- Built-in ROM size : 16K words
(1 word = 16 bits)
- Built-in RAM size :
Work RAM : 512×4 bits
- Input pins : 4 pins (with interrupts)
- I/O pins : 12 pins (with 4 interrupts and mask option)
- Output pins : 1 pin (Buzzer)
- Interruption : 2 external system (input pins, general-purpose I/O pin)
2 internal system (timer / counter, timings)

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- Timer : 8 bits×2ch or 16 bits×1ch (software-selectable)
- LCD display driver controller : 52 seg×16 com
- Built-in LCD driver power circuit
- Watchdog timer : Timer/Counter can be used as Watch Dog Timer
- Power Supply voltage : 1.5/3.0V (Typ.) Mask option

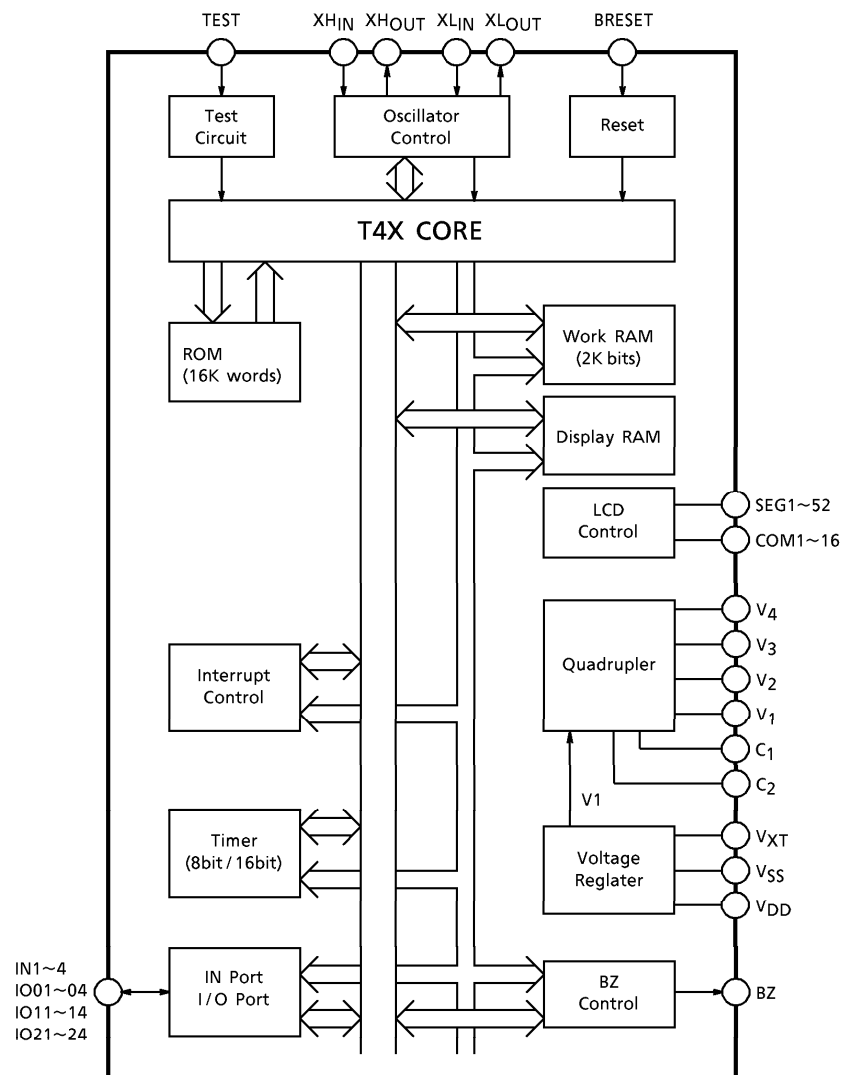


Fig.1 Block diagram

◆PIN CONFIGURATION
1. Pin assignment



PIN No.	PIN NAME
1	V ₁
2	C ₁
3	C ₂
4	V _{SS}
5	VXT
6	BRESET
7	XLIN
8	XLOUT
9	V _{DD}
10	XHIN
11	XHOUT
12	TEST
13	BZ
14	IN1
15	IN2
16	IN3
17	IN4
18	IO01
19	IO02
20	IO03
21	IO04
22	IO11
23	IO12
24	IO13
25	IO14

PIN No.	PIN NAME
26	IO21
27	IO22
28	IO23
29	IO24
30	S ₁
31	S ₂
32	S ₃
33	S ₄
34	S ₅
35	S ₆
36	S ₇
37	S ₈
38	S ₉
39	S ₁₀
40	S ₁₁
41	S ₁₂
42	S ₁₃
43	S ₁₄
44	S ₁₅
45	S ₁₆
46	S ₁₇
47	S ₁₈
48	S ₁₉
49	S ₂₀
50	S ₂₁

PIN No.	PIN NAME
51	S ₂₂
52	S ₂₃
53	S ₂₄
54	S ₂₅
55	S ₂₆
56	S ₂₇
57	S ₂₈
58	S ₂₉
59	S ₃₀
60	S ₃₁
61	S ₃₂
62	S ₃₃
63	S ₃₄
64	S ₃₅
65	S ₃₆
66	S ₃₇
67	S ₃₈
68	S ₃₉
69	S ₄₀
70	S ₄₁
71	S ₄₂
72	S ₄₃
73	S ₄₄
74	S ₄₅
75	S ₄₆

PIN No.	PIN NAME
76	S ₄₇
77	S ₄₈
78	S ₄₉
79	S ₅₀
80	S ₅₁
81	S ₅₂
82	COM16
83	COM15
84	COM14
85	COM13
86	COM12
87	COM11
88	COM10
89	COM9
90	COM8
91	COM7
92	COM6
93	COM5
94	COM4
95	COM3
96	COM2
97	COM1
98	V ₄
99	V ₃
100	V ₂

2. Pin description

PIN NAME	FUNCTION
V _{DD}	Power supply (+)
V _{SS}	Power supply (-)
V _{XT}	Voltage regulator1 output (Output for only the mask option 3.0V type)
V ₁	Voltage regulator2 output
V ₂ ~V ₄	Boosted voltage output
C ₁ , C ₂	Capacitor pin for LCD booster
XHIN, XHOUT	Crystal/resister connection pin for high-speed oscillator
XLIN, XLOUT	Crystal connection pin for low-speed oscillator
IN ₁ ~IN ₄	Input port (with interruption)
IO ₀₁ ~IO ₀₄	I/O port (with interruption)
IO ₁₁ ~IO ₁₄	I/O port
IO ₂₁ ~IO ₂₄	I/O port
SEG ₁ ~SEG ₅₂	LCD segment output
COM ₁ ~COM ₁₆	LCD common output
BZ	Buzzer output
BRESET	Reset input (low active)
TEST	Test input

◆MEMORY MAP

1. Program ROM

Program ROM consists of 16 bits per 1 word. Op-code and operand are executed in one word units. Program ROM consists of 4K words per page. The internal program ROM area is 4 pages (16K words).

This program ROM area can be used for constant data ROM. In this case, it can be used in byte units (1 byte = 8 bits).

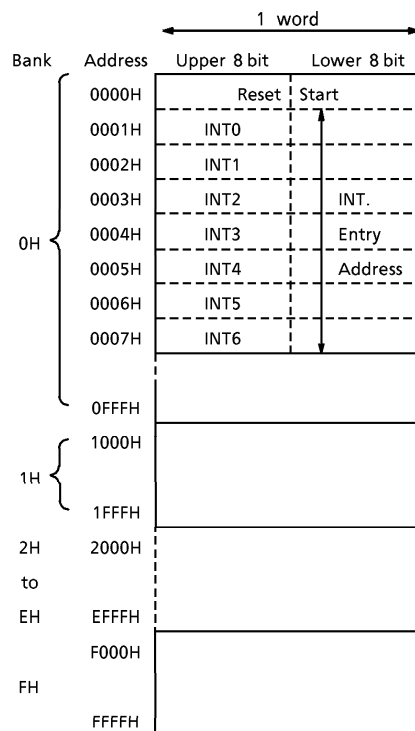


Fig.2 Program memory map

(Note) Use the CALL instruction to write the interrupt entry address. Write NOP for unused interrupts.

Example : CALL A ; INT0
 NOP ; IN1
 CALL B ; IN2
 NOP ; IN3
 NOP ; IN4
 NOP ; IN5
 NOP ; IN6

2. Work RAM

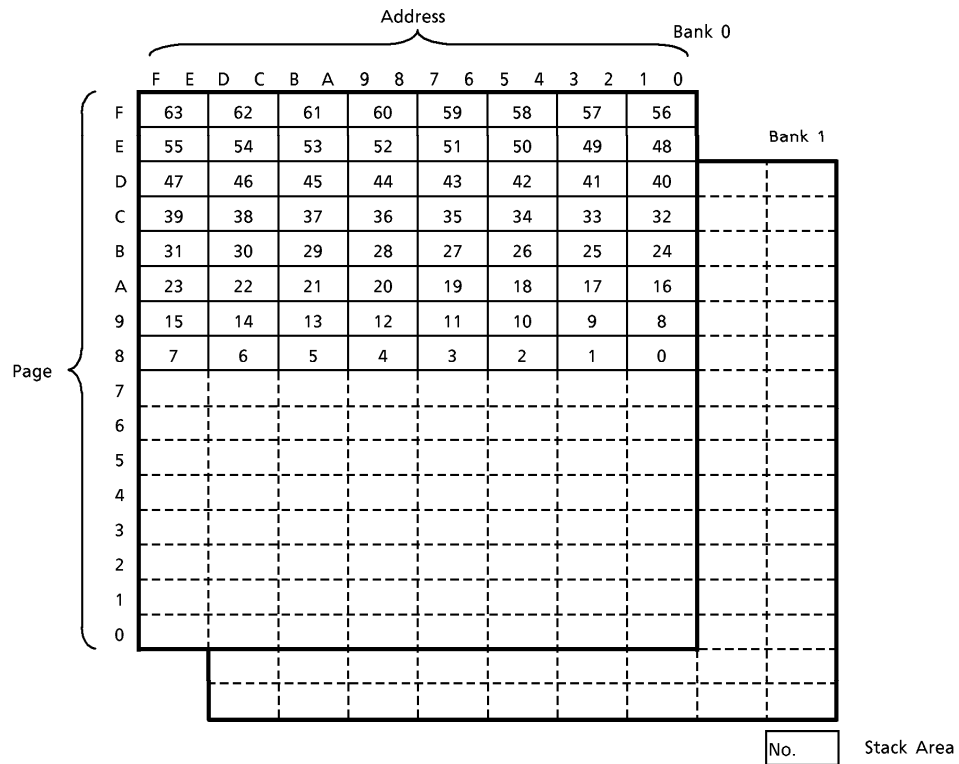


Fig.3 Work RAM

Work RAM consists of 512×4 bits.

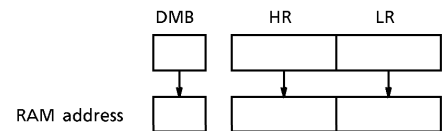
R/W is performed at the address specified by bellows.

(1) Indirectly addressing mode (Fig.4 (a))

DMB in F-reg, H, L-reg specify the Work RAM address.

(DMB : bank, H-reg : page, L-reg : address)

LD A, M : $A \leftarrow \text{RAM}(\text{HL})$



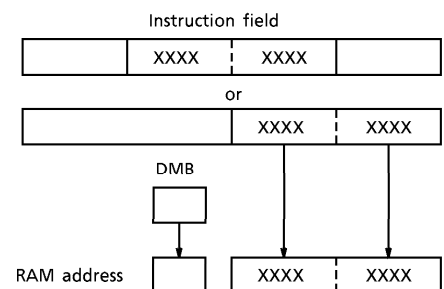
(a) Indirectly addressing

(2) Directly addressing mode (Fig.4 (b))

Immediate data (8 bits) in instruction specify the Work RAM page and address.

Bank is specified by DMB in F-reg.

LDI 2CH, 0AH : $\text{RAM}(2\text{CH}) \leftarrow \text{AH}$



(b) Directly addressing

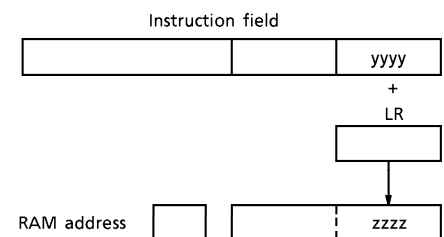
(3) Index addressing mode (Fig.4 (c))

Address (L-reg) is specified by the immediate data (4 bits) in instruction, and the other immediate data specify Page.

LDRI 4H, 3H : $\text{RAM}(\text{HL} + 4\text{H})$

$\leftarrow \text{RAM}(3\text{H}, \text{L})$

$\text{L} \leftarrow \text{L} + 1, \text{A} \leftarrow \text{A} - 1$



(c) Index addressing

Fig.4 Addressing mode

BANK 0, PAGE 8~F area can be used as Stack area.

When using the "CALL/CALLS" instruction or start the interruption routine, the data of program counter and Program memory bank are stored in Stack area.

Then, using "RET" instruction, program return according to those data.

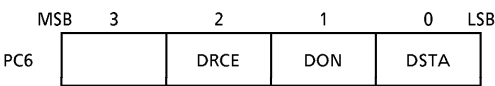
And, using "PUSH" instruction, 8 bits data in a pair register can be stored in Stack area.

Then, using "POP" instruction, those data are returned to the register.

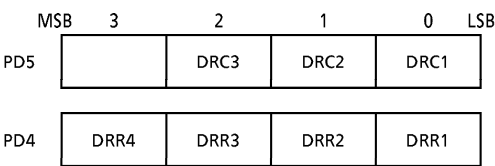
Maximum Stack area is 64 (0~63), and each Stack area consist of 8 bits.

3. Display RAM

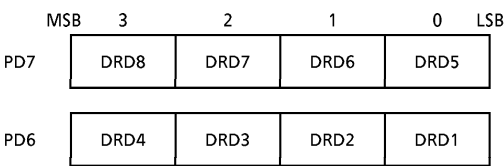
TMP04CH01FXXX has Display RAM, and addressing and data read/write is decided by Register file, as follows. When the data is read from/written into Display RAM. DRCE (PC6-bit2) is needed to be 1.



Addressing is decided by DRR1~4 (PD4) and DRC1~3 (PD5) (LSB is DRR1, and MSB is DRC3)



Data is read/written by 8 bits which is set in DRD1~8 (PD6, PD7).
To read from/written into DISPLAY, only 8 bits transference instruction can be used.



(CAUTION)

- 1. When “HALT” instruction is executed for the next instruction of the transference the data to Display RAM, the data of Display RAM is broken.
- 2. When “HALT” instruction is executed during DRCE1 is 1, the data of Display RAM is broken. Therefore, be sure to set DRCE to 0 before executing the HALT instruction.
DRD1 to 8 (R56, R57) are valid for only 8-bit transfer instructions.
4-bit transfer instructions do not have any effect (NOP).

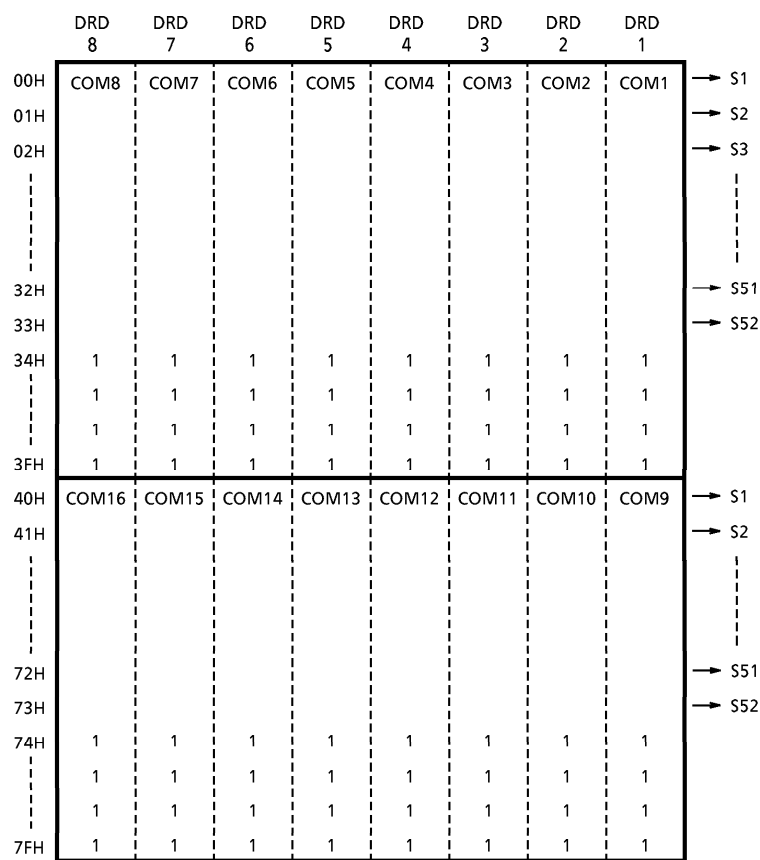


Fig.5 Display RAM

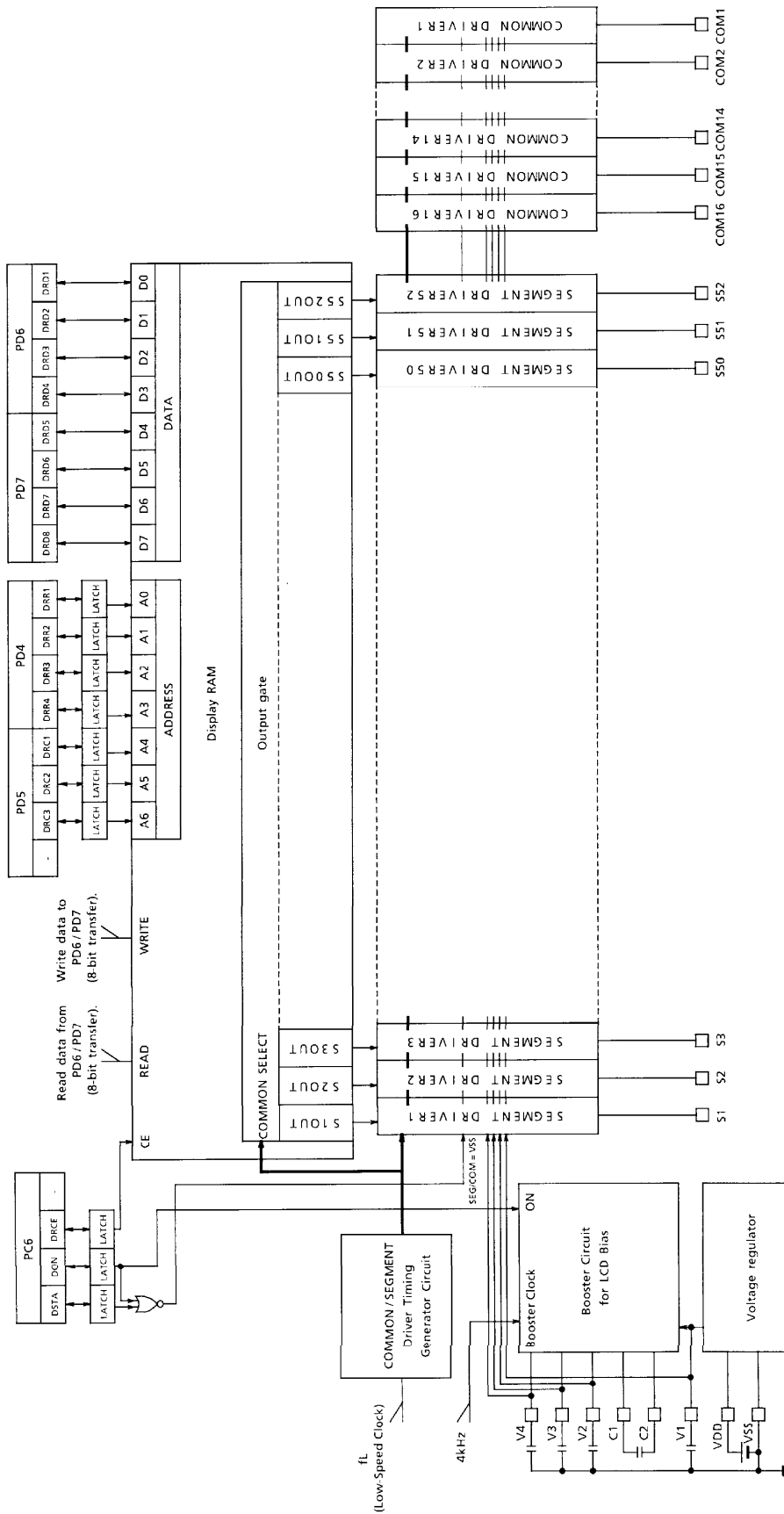


Fig.6 LCD Driver

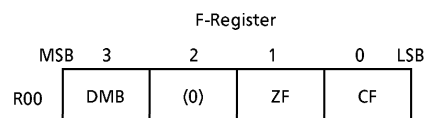
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◆REGISTER FILE

Register files consist of 1. general-purpose registers, 2. system registers, and 3. peripheral I/O registers. Figure 11 shows the overall configuration of register files.

1. General Register

1.1 Flag Register : F-Register (PAGE / AD = 0 / 0)



CF : Carry Flag
 ZF : Zero Flag
 (0) : Not use
 DMB : Work RAM Bank

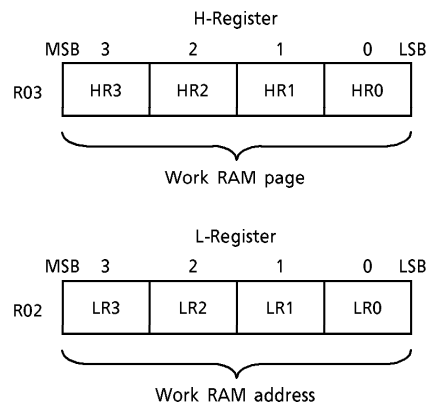
1.2 Accumulator Register : A-Register (PAGE / AD = 0 / 1)

Accumulator for arithmetic operations.

When consecutive instructions are executed, used as a counter register.

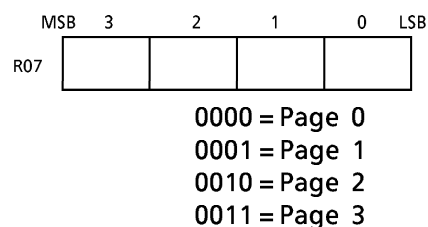
1.3 H.L Register (PAGE / AD = 0 / 3~2)

H.L Register are used for Work RAM address setting with DMB.



1.4 Bank Register (PAGE / AD = 0 / 7) : B-Register

B-Register is used for ROM Page.



1.5 D-Register, E-Register, P-Register, (B-Register) (PAGE / AD = 0 / 5, 0 / 4, 0 / 6, 0 / 7)

General-purpose register.

When using ROM as Data Table Function, B, P, D and E-Register are used for ROM address setting.

(Data table function : user can use ROM area for store the constant, and can access those constant by LDBL or LDBH instruction.)

2. System Registers

2.1 Stack pointer (PAGE / AD = 1 / 0, 1 / 1)

The stack pointer shows the location (63 to 0) in the stack area in work RAM.

	MSB	3	2	1	0
R10		SP4	SP2	SP1	—

	MSB	3	2	1	0
R11		—	SP32	SP16	SP8

2.2. Interrupt Enable / Disable Registers (PAGE / AD = 1 / 2, 1 / 3)

Enable/disable interrupts. There are five interrupt vectors (INT0 to INT4). Writing data in the bit corresponding to an interrupt enables/disables the interrupt. The details are described in the section on peripheral circuits.

	MSB	3	2	1	0
R12		INT2	INT1	INT0	(0)

	MSB	3	2	1	0
R13		—	—	INT4	INT3

2.3. Input / Output Registers (PAGE / AD = 1 / 4, 1 / 5)

Used for the input/output pins (IO21 to IO24). Using the bit that corresponds to a pin, output data can be set or input data can be read. The details are described in the section on peripheral circuits.

	MSB	3	2	1	0
R14		IO14	IO13	IO12	IO11

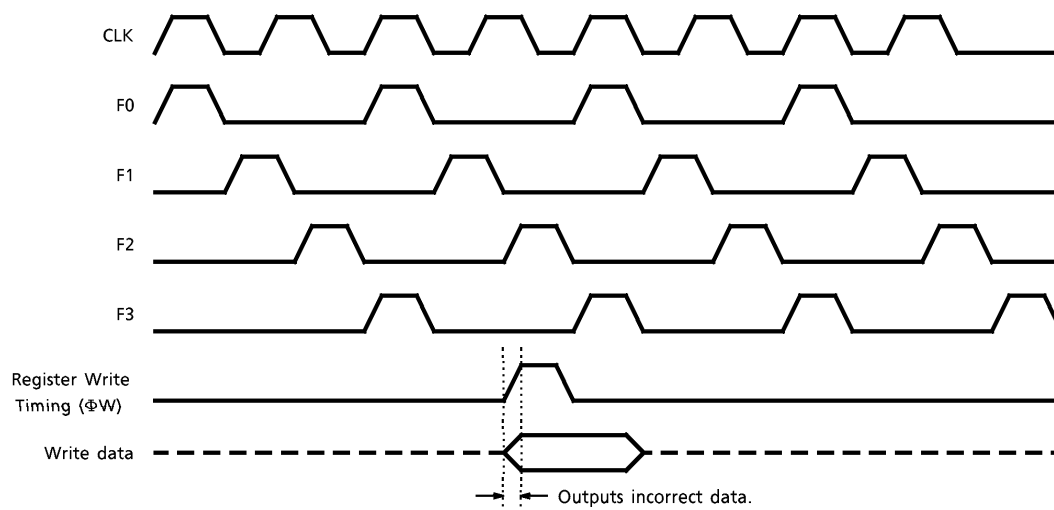
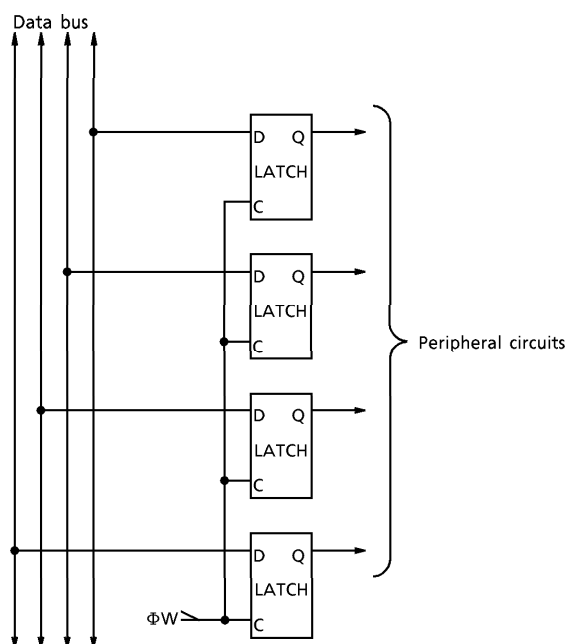
	MSB	3	2	1	0
R15		IO24	IO23	IO22	IO21

3. Peripheral I / O Registers

Registers used to control peripheral circuits specific to the product are allocated to pages 2 to 7. The details are described in the section on peripheral circuits.

※ A precaution relating to Writes to System Registers/Peripheral I/O Registers.

Writing to System Register and I/O Registers is performed in synchronization with ΦW . Because rising edges of ΦW coincides with the timing at which Write data is output on the data bus, it is possible that incorrect data is output to the peripheral circuits for a very short period of time. Please take this into account when programming.



PAGE (RFB)	ADDRESS		0		1		2		3		4		5		6		7	
	8BIT		0		1		2		3		4		5		6		7	
	ADDRESS		LOWER4BIT		UPPER4BIT		L4BIT		H4BIT		L4BIT		H4BIT		L4BIT		H4BIT	
	R/W		READ	WRITE	READ	WRITE	READ	WRITE	READ	WRITE	READ	WRITE	READ	WRITE	READ	WRITE	READ	WRITE
0	MSB	BIT3																
		BIT2																
		BIT1																
	LSB	BIT0																
1 (P1x)	MSB	BIT3																
		BIT2																
		BIT1																
	LSB	BIT0																
2 (PAX)	MSB	BIT3																
		BIT2																
		BIT1																
	LSB	BIT0																
3 (PBx)	MSB	BIT3																
		BIT2																
		BIT1																
	LSB	BIT0																
4 (PCx)	MSB	BIT3																
		BIT2																
		BIT1																
	LSB	BIT0																
5 (PDx)	MSB	BIT3																
		BIT2																
		BIT1																
	LSB	BIT0																
6 (PEx)	MSB	BIT3																
		BIT2																
		BIT1																
	LSB	BIT0																
7 (PFx)	MSB	BIT3																
		BIT2																
		BIT1																
	LSB	BIT0																

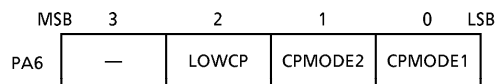
Fig.7 Register file

(Note) Blank columns are indeterminate.

◆PERIPHERAL CIRCUIT

Each peripheral circuits can be accessed (Read / Write / Circuit setting) by Register files.

1. Oscillator Block



The CPU clock is generated by the asynchronous oscillator switching circuit which has low-speed and high-speed clock oscillator circuit.

This block also provides the clock for the timer circuit, LCD driver, Quadrupler.

Oscillation mode is controlled by Register file CPMODE1 and CPMODE2 (PAGE / AD = 2 / 6), as follows.

CPMODE 1	CPMODE 2	Low- speed OSC	High- speed OSC	SYSTEM CP	MODE name
0	0	OFF	OFF	OFF	(CPM0)
1	0	ON	OFF	Low speed	(CPM1)
0	1	OFF	ON	High speed	(CPM2)
1	1	ON	ON	High speed	(CPM3)

CPMODE 1 and 2 are initially 1 (CPM3)

LOWCP is the display clock control bit. When LOWCP is set to 1, Low-speed OSC clock is supplied to LCD circuit. LOWCP is initially "0". Even if LOWCP is set to 1, clock cannot be occupied to display circuit during Low-speed OSC stopped, and display cannot be shown.

Low-speed OSC circuit can select X'tal or internal CR oscillation by Mask option.

High-speed OSC circuit can select X'tal or external CR oscillation by Mask option.

Setting a register to CPM1 and executing a HALT instruction sets the mode to Halt (system CP off, high-speed oscillator off, low-speed oscillator on). Setting a register to CPM0 and executing a HALT instruction sets the mode to Stop (system CP off, high-speed oscillator and low-speed oscillators off). Even if, mode is changed to MODE 0 from MODE 1 / 2 / 3, there are no changing until use HALT instruction.

The High / Low-speed OSC circuit has WARM UP function.

The warm-up function disables the crystal oscillator as the system clock from when the crystal oscillator starts oscillation to when the frequency stabilizes. The warm-up circuit in the high-speed crystal oscillator circuit consists of a 15-stage binary counter. The warm-up time is 16,384 pulses of the high-speed clock. The warm-up circuit in the low-speed crystal oscillator circuit consists of a 9-stage binary counter. The warm-up time is 256 pulses of the high-speed clock.

The low-speed oscillation does not have enough warm-up time, therefore, when the oscillation is started, software need to make warming up time enoughly.

Set the warm-up time by software to approx. 500 ms as standard.

When the System CP is changed between Low and High (CPM1→CPM2 / 3 or CPM2→CPM1), changing System CP waits to finish the warming up time.

Also that until the system CP is changed, instructions are executed with the previous system CP.

If the CR oscillator is selected as the high- or low-speed oscillator circuit, the warm-up function is disabled.



The divider circuit of bits 1 to 6 generates a clock from 1 MHz to 32 kHz by dividing the high-speed clock (2 MHz). The divider circuit of bits 7 to 21 generates a clock from 16 kHz to 1 Hz by dividing the 32 kHz clock. When the low-speed oscillator circuit is on (CPM1/CPM3), a low-speed clock (32 MHz) is supplied to the divider circuit of bits 7 to 21. When the low-speed oscillator circuit is off (CPM2), output from bit 6 is supplied.



	MSB	3	2	1	0	LSB
PA7W		RST4	RST3	RST2	RST1	

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(CAUTION)

1. Do not set System CP to low-speed when the Low-speed OSC is not in operation or before stable.
2. Do not set System CP to high-speed when the High-speed OSC is not in operation or before stable.
3. And, when Low-speed OSC is on, low-speed frequency is supplied from 7th bit Divider circuit (When use 2MHz crystal for High-speed OSC and 32kHz crystal for Low-speed OSC and the mode is CPM3, 1MHz~32kHz are made by 2MHz crystal, 16kHz~1Hz are made by 32kHz crystal. And when the mode is CPM2, all frequency are made by 2MHz crystal. Therefore if the mode change between CPM1 and CPM2 or CPM2 and CPM3, the frequency which is supplied by Binary counter 7~21 shift the timing).
4. When operated with a 1.5V power supply, the oscillation frequency on the high-speed side is 200kHz (max.), so that the output of binary counter 6 is 3.125kHz (max.). Consequently, if the mode is changed from CPM1 or 3 to CPM2 or from CPM2 to CPM1 or 3, the generated timing changes greatly.
5. When the crystal oscillator circuit is used for low-speed oscillation, a long time is required from oscillation stop to oscillation start. The LCD circuit operates using a low-speed clock. LCD cannot be performed until oscillation starts. After power on, operate the low-speed oscillator circuit at all times and do not change to STOP mode.

Example 1

```

START mode (After warming up, program start at address 0000.)
↓
CPM3 (High / Low speed ON, SYSCP = High, LOWCP OFF)
↓   LD 26O, 7H
CPM3 (High / Low speed ON, SYSCP = High, LOWCP ON)
↓   LD 26O, 4H
CPM0 (High / Low speed ON, SYSCP = High, LOWCP ON)
    (There are no change after shift to CPM0)
↓   HALT
STOP mode (High / Low-speed OSC, STOP, SYSCP OFF, LOWCP OFF)

```

When an interruption occurs, the mode is changed to START mode and program start at the address which is decided by each interruption (refer to Fig.2).

Example 2

```

START mode (After warming up, program start at address 0000.)
↓
CPM3 (High / Low speed ON, SYSCP = High, LOWCP OFF)
↓   LD 26O, 5H
CPM1 (Low speed ON, SYSCP = Low, LOWCP ON)
↓   HALT
HALT mode (High-speed OSC OFF, Low-speed OSC ON, SYSCP OFF, LOWCP ON)

```

When an interruption occurs, the mode is changed to slow mode (CPM1) and program start at the address which is decided by each interruption.

Example 3

START mode (After warming up, program start at address 0000.)

↓

CPM3 (High / Low speed ON, SYSCP = High, LOWCP OFF)

↓

LD 26O, 7H

CPM3 (High / Low speed ON, SYSCP = High, LOWCP ON)

↓

LD 26O, 4H

CPM0 (High / Low speed ON, SYSCP = High, LOWCP ON)

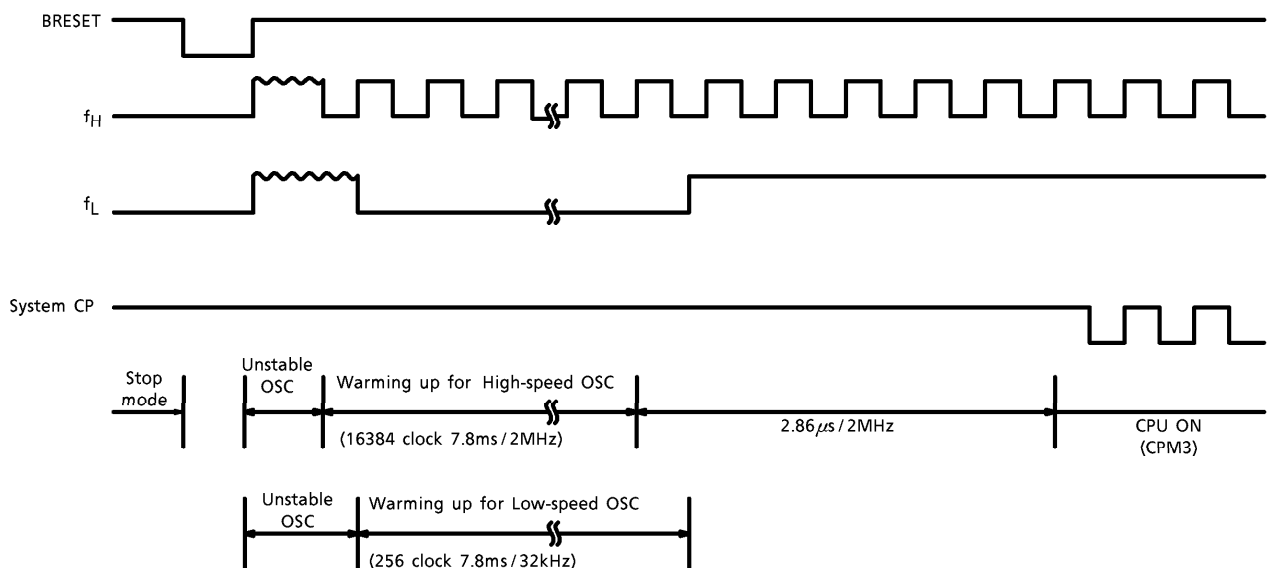
(There are no change after shift to CPM0.)

↓

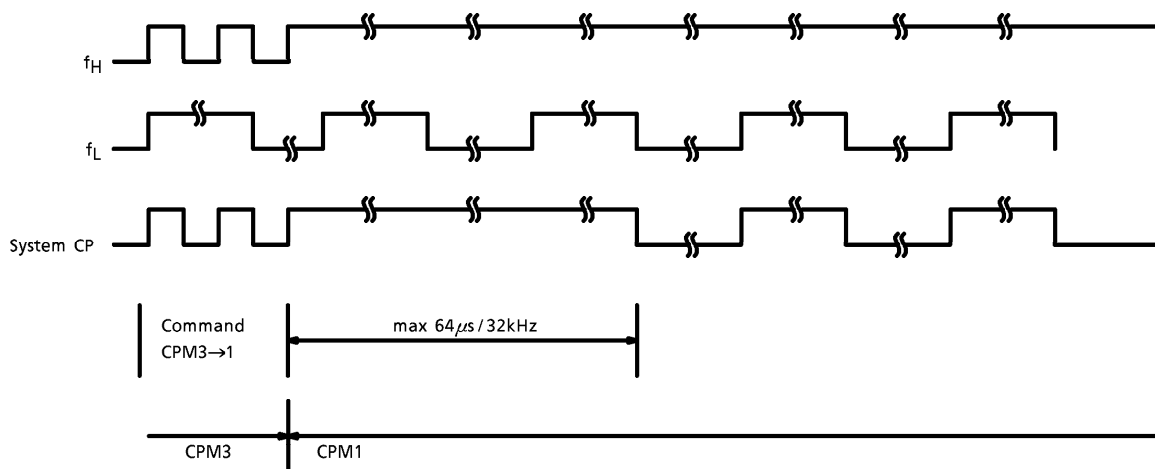
LD 26O, 7H

CPM3 (High / Low speed ON, SYSCP = High, LOWCP ON)

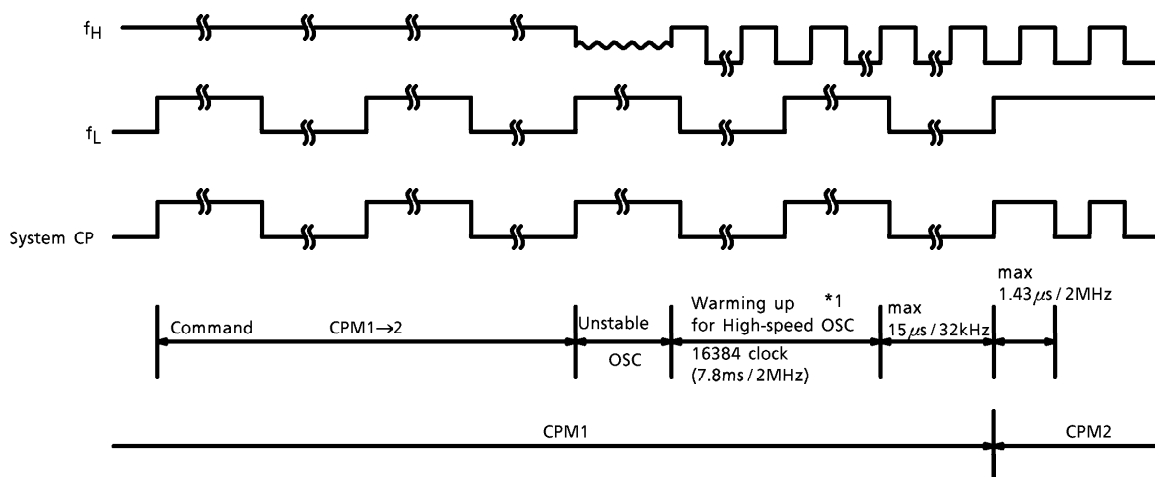
Example 4 (After reset)



Examples (CPM3→1)



Example (CPM1→2)



(Note) No warm-up is provided for high-speed and low-speed RC oscillations by mask options.



Fig.10 Oscillator circuit / Divider circuit

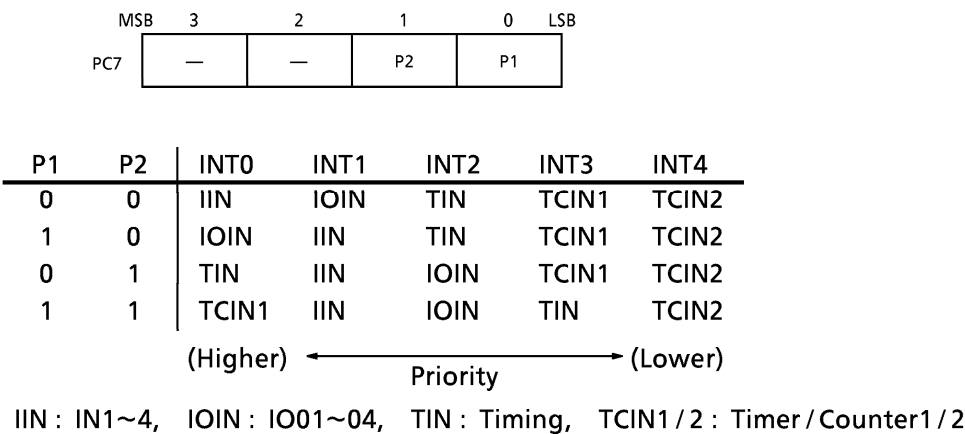
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2. Interruption Block

Interruption is supplied by IN1~4, IO01~04, Timer / Counter, Timing.

(Interruption Priority)

Interruption priority can be selected by Register file P1 and P2.
Interrupt priority is valid only when multiple interrupts occur simultaneously.
P1, P2 are initially 0.



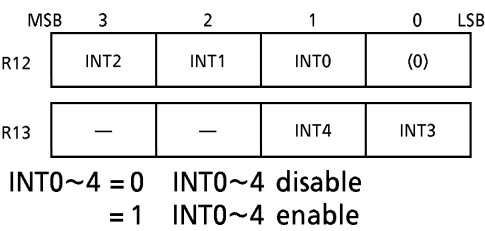
(Interruption enable / disable)

Each interruption (IIN, IOIN, TIN, TCIN1, TCIN2) is decided disable / enable as follows.

- IIN : IIE1~4 (R42-B0~3)
- IOIN : IOIE0 (R43-B0)
- TIN : TIE1~4 (R53-B0~3)
- TCIN1 : TCI1E (R64-B1)
- TCIN2 : TCI2E (R74-B1)

After deciding priority by P1, P2 each interruption is decided disable / enable by INT0~4.
Disable the unnecessary interrupts in your application by initial settings of IIE1-4, IOIE, TIE1-4, and TCI1E / 2E.

INT0~4 are initially 0 (disable).



Interrupt reset

After an interrupt occurs, reset the interrupt following the procedures described below.
First, reset IN1~IN4 interrupt / IO01~IO04 Interrupt / Timing Interrupt / Timer Counter 1 Interrupt / Timer counter 2 Interrupt.
Then reset the signal "Release from HALT / STOP Mode" by executing a transfer instruction to R12 or R13.
How to deactivate respective interrupts will be explained in the sections which describe each of the interrupts.

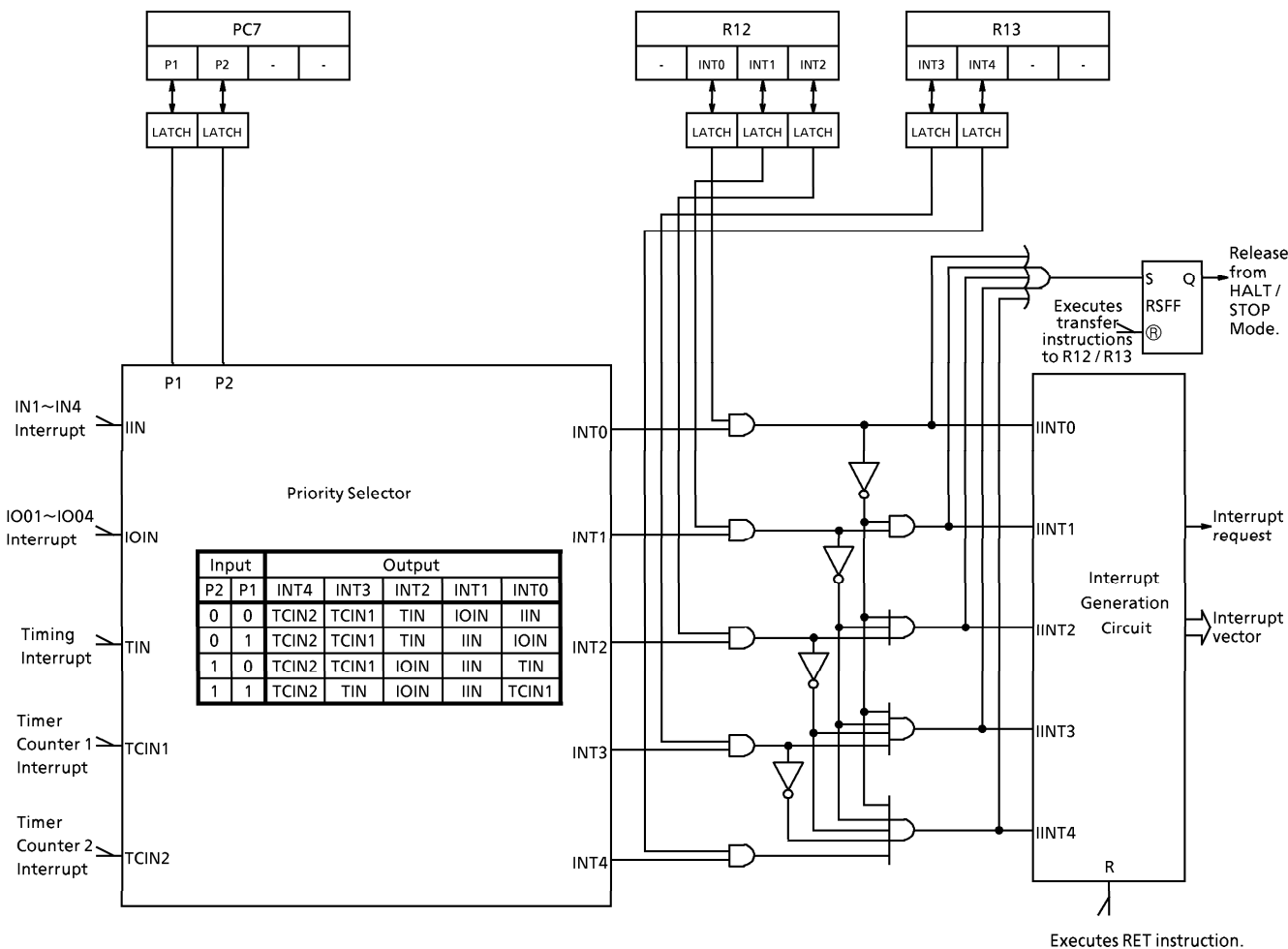
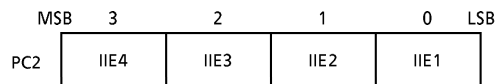


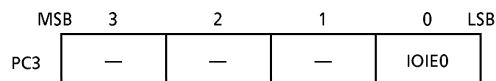
Fig.11 Interruption circuit block

2.1 Input/Inoutput Interruption (Interruption enable/disable)



IIE1 = 0 IN1 Interruption disable
 = 1 IN1 Interruption enable
 IIE2 = 0 IN2 Interruption disable
 = 1 IN2 Interruption enable
 IIE3 = 0 IN3 Interruption disable
 = 1 IN3 Interruption enable
 IIE4 = 0 IN4 Interruption disable
 = 1 IN4 Interruption enable

IIE1~4 are initially 0 (IN1~4 Interruption disable)



IOIE0 = 0 IO01~4 Interruption disable
 = 1 IO01~4 Interruption enable

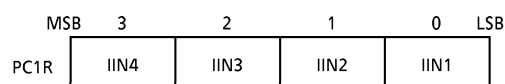
IOIE0 is initially 0 (disable)

Interruption enable/disable bit can use as interruption reset.

When the interruption occurs and after recognizing the interruption, it can be resetted INT latch by setting IIE1~4 or IOIE0.

(Interruption Data Read)

Interruption Data of IN1~4 can be read by Register file IIN1~4.



Example

```

LD 420, 0FH  (set enable to IN1~4 interruption)
  ↓
  IN1 interruption occurs.
  ↓
  Program goes to the address which is decided by each interruption.
LD M. 4IO    (read IN1~4 interruption)
  ↓
  Recognize which interruption is occurred.
  (Recognize IN1 interruption is occurred.)
LD 420, 0EH  (reset IN1 interruption)
  ↓
LD 120, 0FH  (set enable to INT0~2)
  ↓
LD 130, 0FH  (set enable to INT3~4)
  ↓
LD 420, 0FH  (set enable to IN1~4 interruption)
  
```

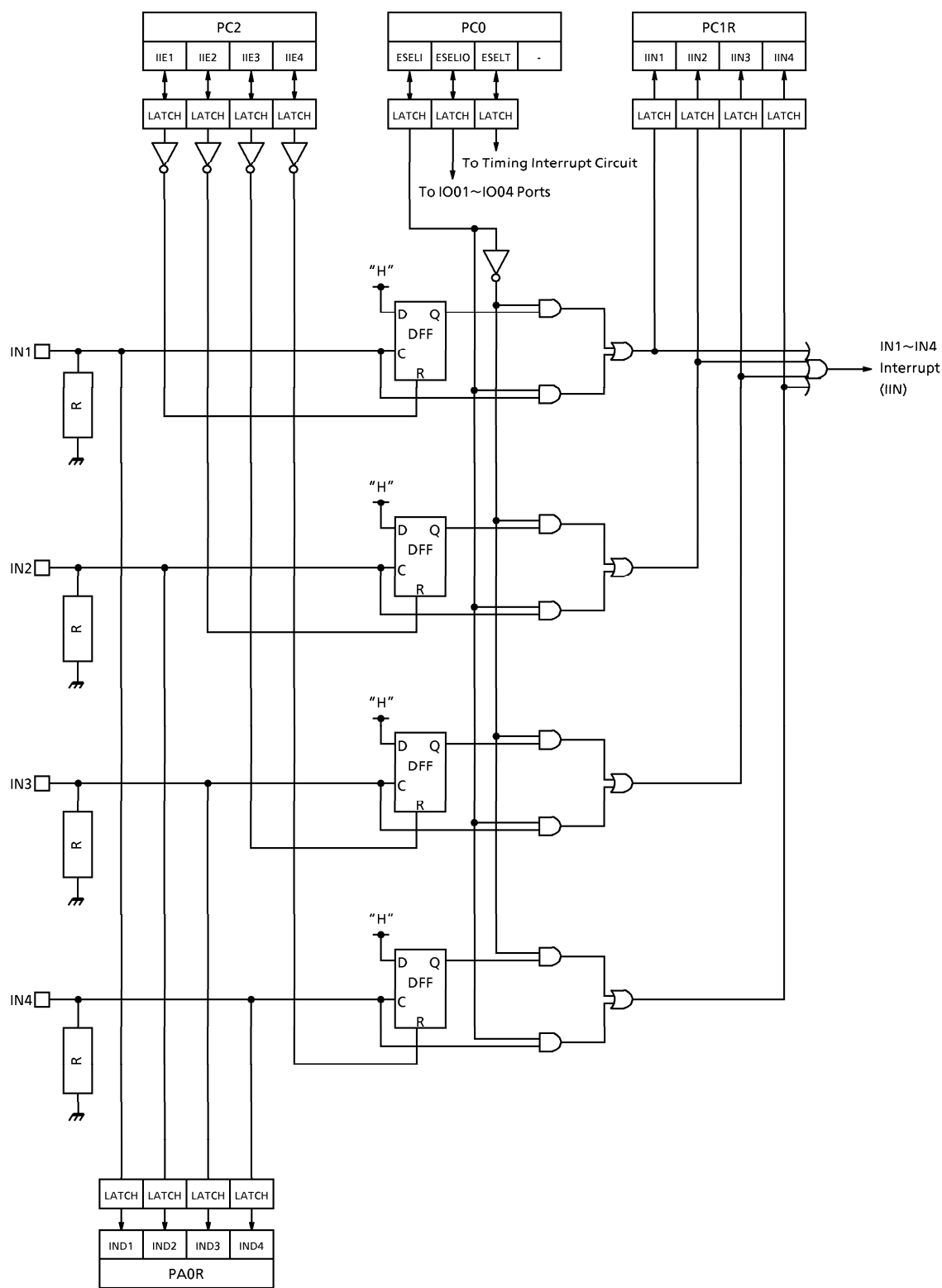


Fig.12 IN1~IN4 Interrupts



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2.2 Timing Interruption

(Timing Interruption selecting)

Timing Interruptions are selectable by Register file (PD1) 128/256, 16/32, 4/8, 1/2.

	MSB	3	2	1	0	LSB
PD1		1 / 2	4 / 8	16 / 32	128 / 256	

128 / 256	= 0	128Hz	INT. select
	= 1	256Hz	INT. select
16 / 32	= 0	16Hz	INT. select
	= 1	32Hz	INT. select
4 / 8	= 0	4Hz	INT. select
	= 1	8Hz	INT. select
1 / 2	= 0	1Hz	INT. select
	= 1	2Hz	INT. select

128/256, 16/32, 4/8 and 1/2 are initially 0 (1Hz, 4Hz, 16Hz and 128Hz is selected).

(Timing Interruption enable/disable)

Selected Timing Interruption can be controlled enable/disable by Register file (PD3) TIE1~4 (R53).

	MSB	3	2	1	0	LSB
PD3		TIE4	TIE3	TIE2	TIE1	

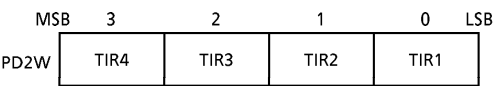
TIE1	= 0	1Hz	or 2Hz	INT. disable
	= 1	1Hz	or 2Hz	INT. enable
TIE2	= 0	4Hz	or 8Hz	INT. disable
	= 1	4Hz	or 8Hz	INT. enable
TIE3	= 0	16Hz	or 32Hz	INT. disable
	= 1	16Hz	or 32Hz	INT. enable
TIE4	= 0	128Hz	or 256Hz	INT. disable
	= 1	128Hz	or 256Hz	INT. enable

TIE1~4 are initially 0 (disable).

(Timing Interruption Reset)

The timing interruption for the selected timing interruption is reset by register files TIR1 to 4 (PD2W).

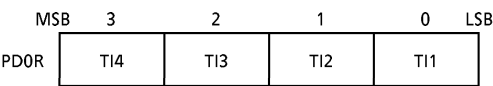
TIR1~4 are initially 0.



- TIR1 = 1 : 1Hz or 2Hz Interruption reset
- TIR2 = 1 : 4Hz or 8Hz Interruption reset
- TIR3 = 1 : 16Hz or 32Hz Interruption reset
- TIR4 = 1 : 128Hz or 256Hz Interruption reset

(Timing Interruption Read)

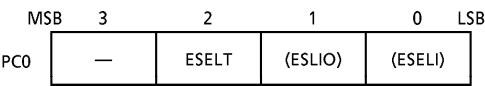
Selected Timing Interruption can be read by Register file TI1~4 (PD0R).



- TI1 : Interruption data of 1Hz or 2Hz
- TI2 : Interruption data of 4Hz or 8Hz
- TI3 : Interruption data of 16Hz or 32Hz
- TI4 : Interruption data of 128Hz or 256Hz

(Interruption Edge Selection)

TIN Interruption can be selected the reading point ( or ) by Register file ESELT. ESTLT is initially 0 (rising EDGE).



- ESELT = 0 : Interruption at rising Edge of Timing INT.
- = 1 : Interruption at down Edge of Timing INT.

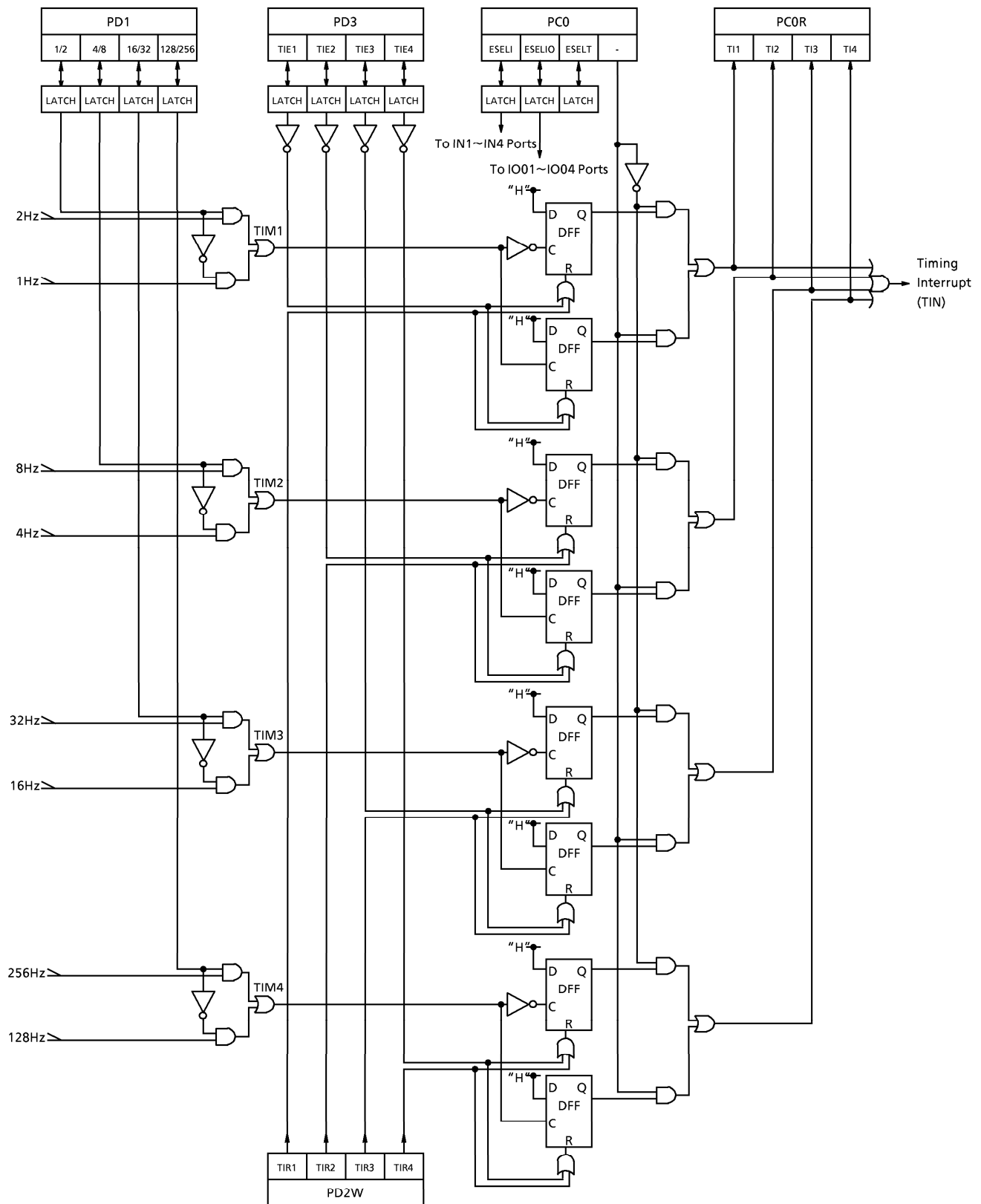


Fig.14 Timing Interrupt Circuit

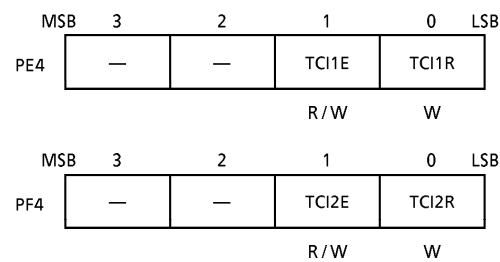
Example

LD 51O, 01H (256Hz, 16Hz, 4Hz and 1Hz select)
↓
LD 53O, 07H (256Hz disable, 16Hz, 4Hz and 1Hz enable)
↓ When the 1Hz interruption occurs.
LD M, 50O (read timing interruption)
↓ Recognize 1Hz interruption.
LD 52O, 01H (reset 1Hz interruption)

(Note) A mode transition from CPM1 or 3 to CPM2 or from CPM2 to CPM1 or 3 causes the timings of binary counters 7-21 to change. Therefore, the timing interrupts also have their timings changed.

2.3 8 bits/16 bits Timer Counter Interruption

When Timer/Counter1, 2 overflow or coincide with setting Time/Count each Interruption occurs.



TCI1E/TCI2E = 0 : Timer/Counter1, 2 Interruption disable
 = 1 : Timer/Counter1, 2 Interruption enable
TCI1R/TCI2R = 1 : Timer/Counter1, 2 Interruption reset

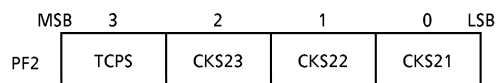
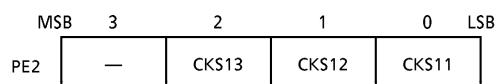
TCI1E, TCI2E and TCI2R are initially 0 (DISABLE).

3. Timer/Counter

The Timer/Counter circuit can use as 8bit×2ch or 16bit ×1ch Timer/Counter.

And there Time/Counter can be use as general-purpose Timer/Counter, Watch Dog Timer, or Multi Interruption Timer.

8 bits/16 bits can be changed by Register file TCPS. And input frequency also can be changed by Register CKS11~13 and CKS21~23, as follows.



CKS 11	CKS 12	CKS 13	Input Frequency for Timer Counter1 ($f_H = 2\text{MHz}$, $f_L = 32\text{kHz}$)		
0	0	0	$f_H / 2^{21}$ ($f_L / 2^{15}$)	1Hz	(1.0s)
1	0	0	$f_H / 2^{12}$ ($f_L / 2^6$)	512Hz	(1.95 μs)
0	1	0	$f_H / 2^8$ ($f_L / 2^2$)	2^{13}Hz	(122 μs)
1	1	0	$f_H / 2^3$	2^{18}Hz	(3.81 μs)
—	—	1	OFF		

CKS 21	CKS 22	CKS 23	Input Frequency for Timer Counter2 ($f_H = 2\text{MHz}$, $f_L = 32\text{kHz}$)		
0	0	0	$f_H / 2^{15}$ ($f_L / 2^9$)	64Hz	(15.6ms)
1	0	0	$f_H / 2^9$ ($f_L / 2^3$)	2^{12}Hz	(244 μs)
0	1	0	$f_H / 2^5$	2^{16}Hz	(15.2 μs)
1	1	0	$f_H / 2^2$	2^{19}Hz	(1.90 μs)
—	—	1	OFF		

TCPS = 0 8bit×2ch Timer/Counter
 = 1 16bit×1ch Timer/Counter

(When Timer/Counter is used as 16 bits timer, TIMER2 is used as lower bits.
 And CKS11~13 are ignored. Input Frequency is decided by CKS21~23.

CKS11~13, CKS21~23 and TCPS are initially 0.

(Timer/Counter1 : 1Hz, Timer/Counter2 : 64Hz, 8bit ×2ch)

(CAUTION)

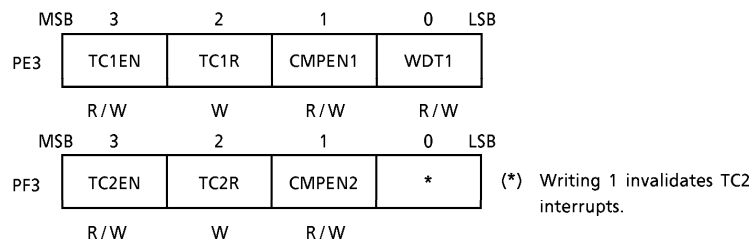
256kHz of Timer/Counter1, 512kHz and 64kHz of Timer/Counter2 can be used when High-speed OSC is on.

Timer function can be selected by REGISTER FILE WDT1 and CMPEN1, 2.

Timer/Counter1 can be used as Watch Dog Timer.

And Input Frequency can be controlled by Register file TC1EN and TC2EN.

Timer/Counter is resetted by Register file TC1R and TC2R.



Timer/Counter1 setting is made in PE3.

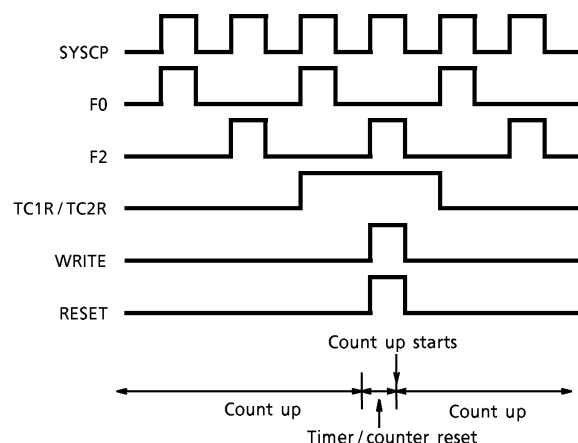
Timer/Counter2 setting is made in PF3.

All the bits of PE3 and PF3 are initially 0.

- PE3 WDT1 = 0 : Used as 8-Bit Timer / Counter.
 = 1 : Used as Watchdog Timer.
- CMPEN1 = 0 : An interrupt is generated if Timer / Counter1 overflows.
 (The entire system is reset if WDT1 = 1.)
 = 1 : An interrupt is generated if Timer / Counter1 values match Time / Count set values. (The entire system is reset if WDT1 = 1.)
- TC1R = 1 : Timer / Counter1 is reset (cleared).
 Timer / Counter1 resumes counting up after reset. (Refer to the timing chart below.)
- TC1EN = 0 : Reference clock input on Timer / Counter1 is stopped.
 = 1 : Reference clock input on Timer / Counter1 is started.
- PF3 BIT0 = 1 : Timer / Counter2 cannot be used as 8-Bit Timer / Counter.
 = 0 : Timer / Counter2 is used as 8-Bit Timer / Counter.
- CMPEN2 = 0 : An interrupt occurs if Timer / Counter2 overflows.
 = 1 : An interrupt occurs if Timer / Counter2 values match Time/Count set values.
- TC2R = 1 : Timer / Counter2 is reset (cleared).
 Timer / Counter2 resumes counting up after reset. (Refer to the timing chart below.)
- TC2EN = 0 : Reference clock input on Timer / Counter2 is stopped.
 = 1 : Reference clock input on Timer / Counter2 is started.

Initially, WDT1 = 0, CMPEN1 / 2 = 0, TC1R / 2R = 0, TC1EN / TC2EN = 0.

Timing chart for timer/counter 1 / 2 reset



Timer/Counter1, 2 data can read from Register file TCR11~18 and TCR21~28.

	MSB	3	2	1	0	LSB
PE0R		TCR14	TCR13	TCR12	TCR11	
PE1R		TCR18	TCR17	TCR16	TCR15	
PF0R		TCR24	TCR23	TCR22	TCR21	
PF1R		TCR28	TCR27	TCR26	TCR25	

Timer/Counter1, 2 Comparison data is set by Register file SET11~18 and SET21~28.

	MSB	3	2	1	0	LSB
PE0W		SET14	SET13	SET12	SET11	
PE1W		SET18	SET17	SET16	SET15	
PF0W		SET24	SET23	SET22	SET21	
PF1W		SET28	SET27	SET26	SET25	

SET11~18 and SET21~28 are initially 0.

(CAUTION)

1. When generating an interrupt for the timer/counter by comparing it with the setup value (SET11-18, SET21-28) or resetting the system, set the setup values in register files SET11-18 and SET21-28 before enabling CMPEN1 and 2.
2. When generating an interrupt by a 16-bit timer by comparing it with the setup value, enable all of CMPEN1, CMPEN2, TC1EN, and TC2EN using instructions.
3. Since the setup values and timer/counter values both are 0 after initialization, an interrupt is generated or the system is reset immediately when CMPEN1 is enabled.
4. Since a mode transition from CPM1 or 3 to CPM2 or from CPM2 to CPM1 or 3 causes the timing of the binary counters 7-21 to change, the timer/counters also have their timings changed.
5. Do not change the timer/counter from 8 bits to 16 bits in the middle of operation after the timer/counter has started counting, because such a change could cause the data to be destroyed.

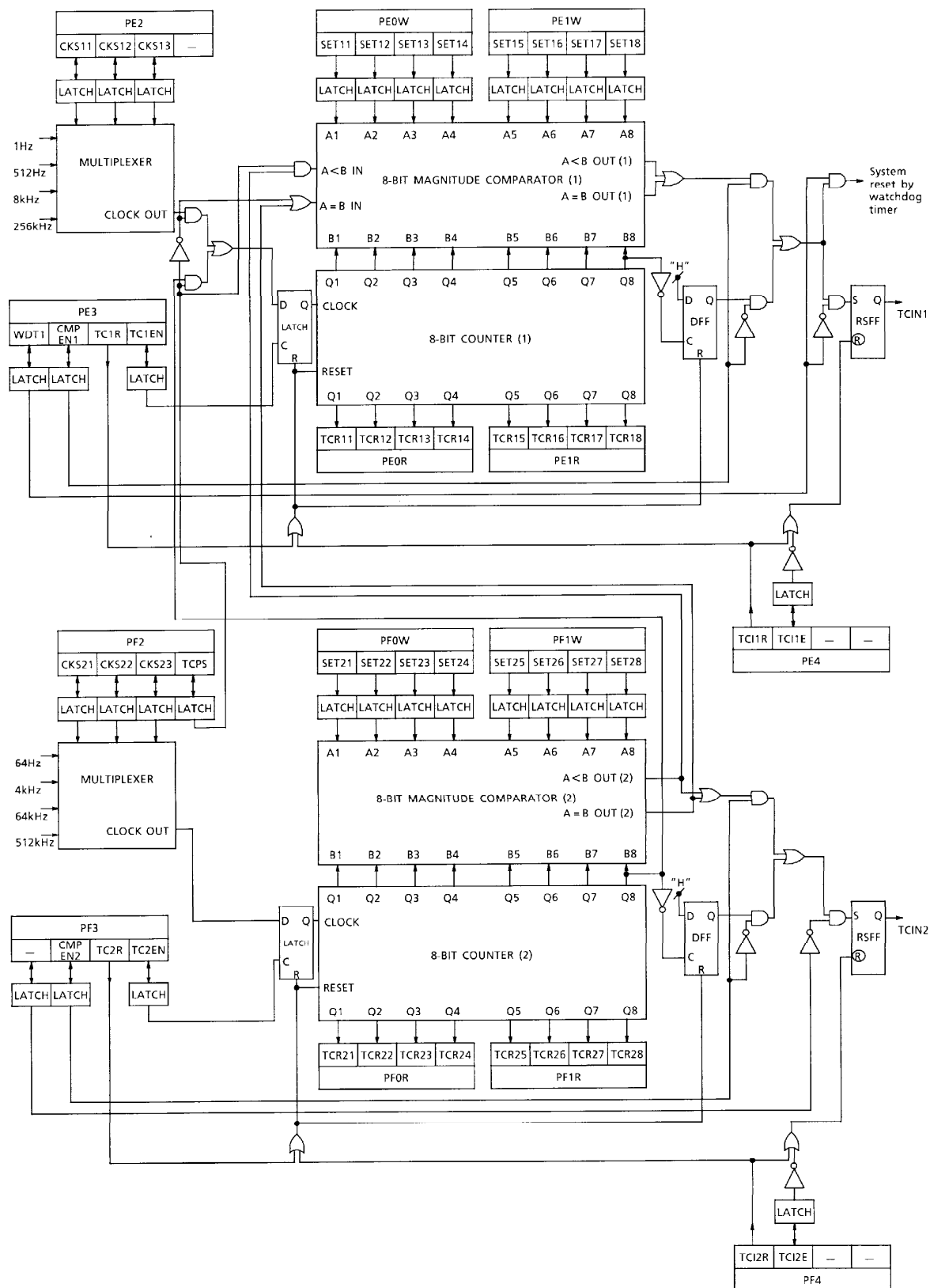


Fig.15 Timer / Counter

4. Input/IO PORTS (Refer to Fig.21)

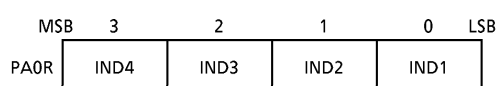
TMP04CH01FXXX has 4 inputs and 12 I/O ports.

4 inputs and 4 I/O ports have Interruption.

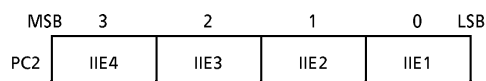
Also, these ports have a mask option available. For details, refer to page 128.

4.1 INPUT (IN1~4)

Each input data can be read by Register file IND1~4.



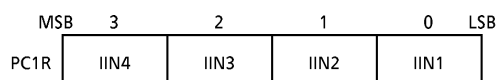
Each input Interruption function can be set enable/disable by Register file IIE1~4.



IIE1~4 = 0 : IN1~IN4 each Interruption disable
 = 1 : IN1~IN4 each Interruption enable

(Note) IIE1 to IIE4 interrupt disable/enables are register files that are effective when rising-edge interrupts are selected.
 When level interrupts are selected, interrupts are disabled/enabled by the data input from ports. In this case, therefore, interrupts cannot be disabled/enabled by the register files.

4 inputs (IN1~4) Interruption data can be read by Register file IIN1~4.



(Note) Interrupt data IO01 to IO04 cannot be read out. Only the data input from ports can be read out. (refer to Fig.13.)
 Interrupt timings (rising edge/level) can be selected using register file ESEL1.

Each input Interruption recognized timing (rising edge / High level) can be selected by Register file ESEL1 (R40 bit1).

	MSB	3	2	1	0	LSB
PC0		—	(ESELT)	(ESELIO)	ESEL1	

ESEL1 = 0 IN1~4 : Interruption at rising edge of input INT.
= 1 IN1~4 : High level of input INT .

Input level-triggered interrupts are possible when ESEL1 = 1. In this case, if interrupts have been enabled by register files INT0-4, the interrupt remain asserted while the input level is high.

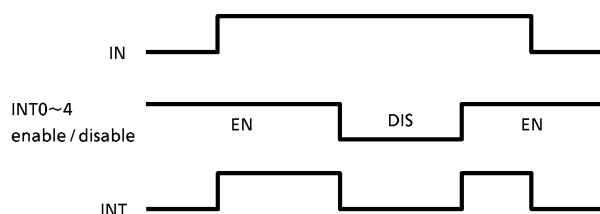


Fig.16 Interruption by high level-read

4.2 I/O ports (IO01~IO04, IO11~IO14, IO21~IO24)

Each input data can be read by following Register file, when using input port.

	MSB	3	2	1	0	LSB
PA1R		IOD04	IOD03	IOD02	IOD01	
R14R		IOD14	IOD13	IOD12	IOD11	
R15R		IOD24	IOD23	IOD22	IOD21	

IO01~IO04 have Interruption, each interruption function can be set disable/enable by Register file IOIE0.

(Four interrupt sources are collectively disabled/enabled by IOIE0.)

	MSB	3	2	1	0	LSB
PC3		—	—	—	IOIE0	

IOIE0 = 0 : IO01~IO04 Interruption disable
 = 1 : IO01~IO04 Interruption enable

(Note) The IO01-IO04 interrupt disable/enables are the register files that are effective when rising-edge interrupts are selected. When level interrupts are selected, interrupts are disabled/enabled by the data input from ports. In this case, therefore, interrupts cannot be disabled/enabled by the register files.

The interrupt data IO01~IO04 cannot be read out. Only the data input from ports can be read out. (refer to Fig.13.)

IO01~IO04 Interruption recognized timing (rising edge/High level) can be selected by Register file ESELIO.

	MSB	3	2	1	0	LSB
PC0		—	(ESELT)	ESELIO	(ESEL)	

ESELIO = 0 : Interruptions IO01~IO04 are rising edge-triggered.
 = 1 : Interruptions IO01~IO04 are level-triggered.

Output data can be read by following Register file, when using each I/O ports as output.

	MSB	3	2	1	0	LSB
PA1W		IOO04	IOO03	IOO02	IOO01	
R14W		IOO14	IOO13	IOO12	IOO11	
R15W		IOO24	IOO23	IOO22	IOO21	

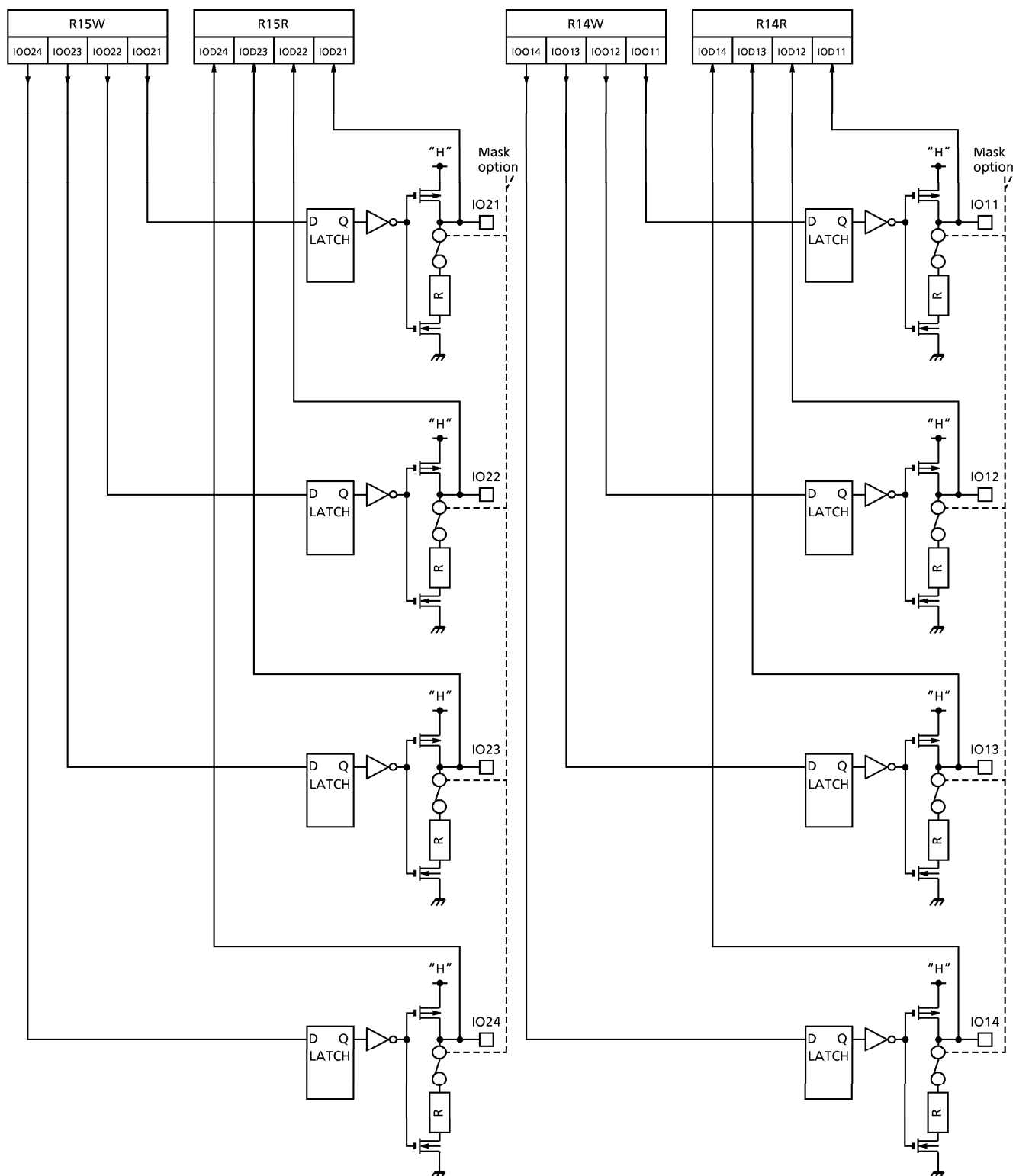


Fig.17 IO11~IO14, IO21~IO24

5. Buzzer Circuit

Buzzer sound can be selected by Register file BZ1, BZ2, BZ3 and 2k/4k.

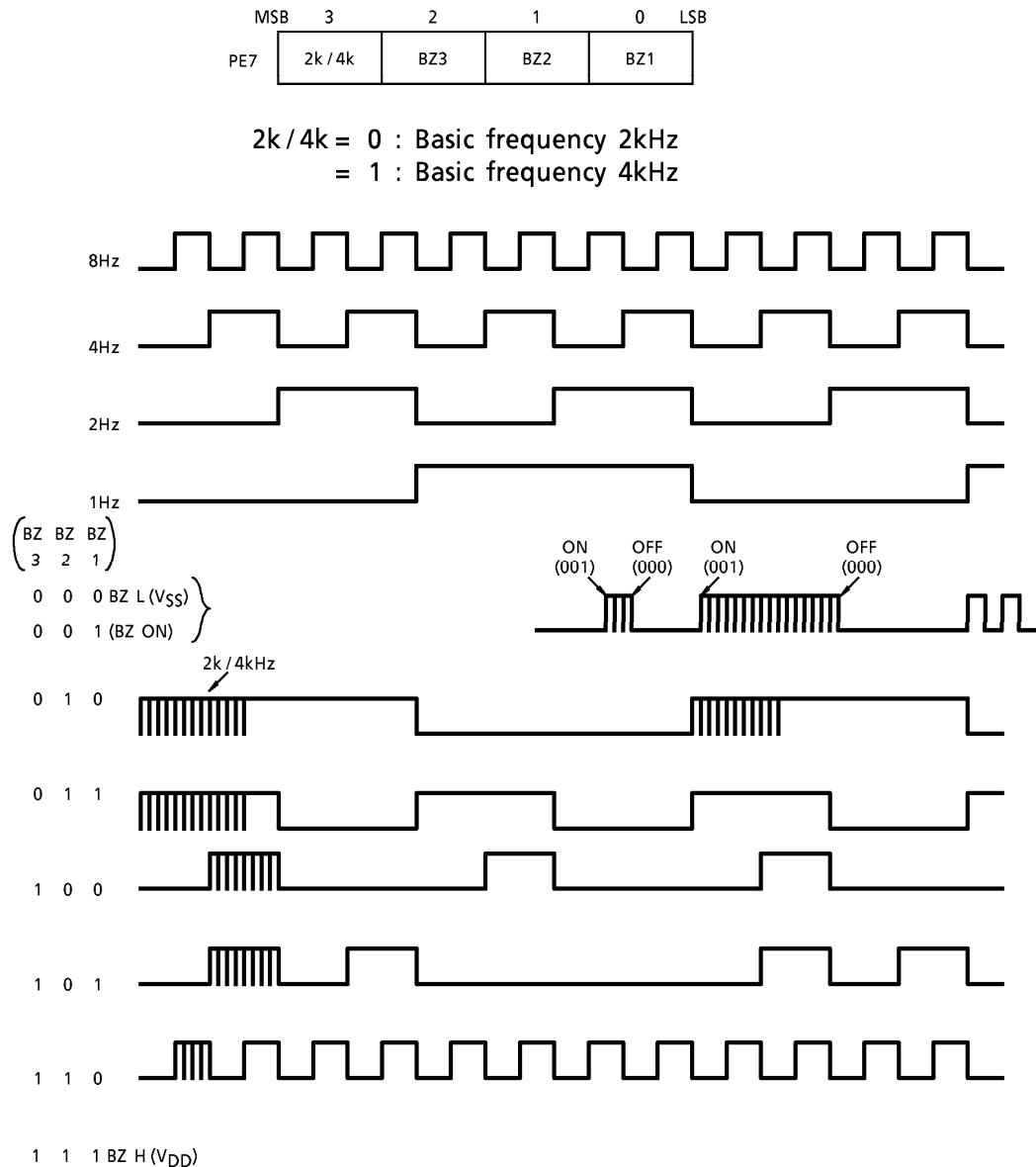


Fig.18 Buzzer sound

Buzzer sound can be made by software using (000), (001) or (000), (111) setting, as above. When the Register file R67 is set the above (BZ3, BZ2, BZ1) = (010)~(110), each Buzzer sound is continuously released setting (BZ3, BZ2, BZ1) to (000).

(Note) The above Buzzer sounds are shown with respect to timings in the CPM2 mode where the high-speed oscillation frequency is 2MHz, the CPM1/3 mode where the low-speed oscillation frequency is 32kHz, and in the HALT mode.

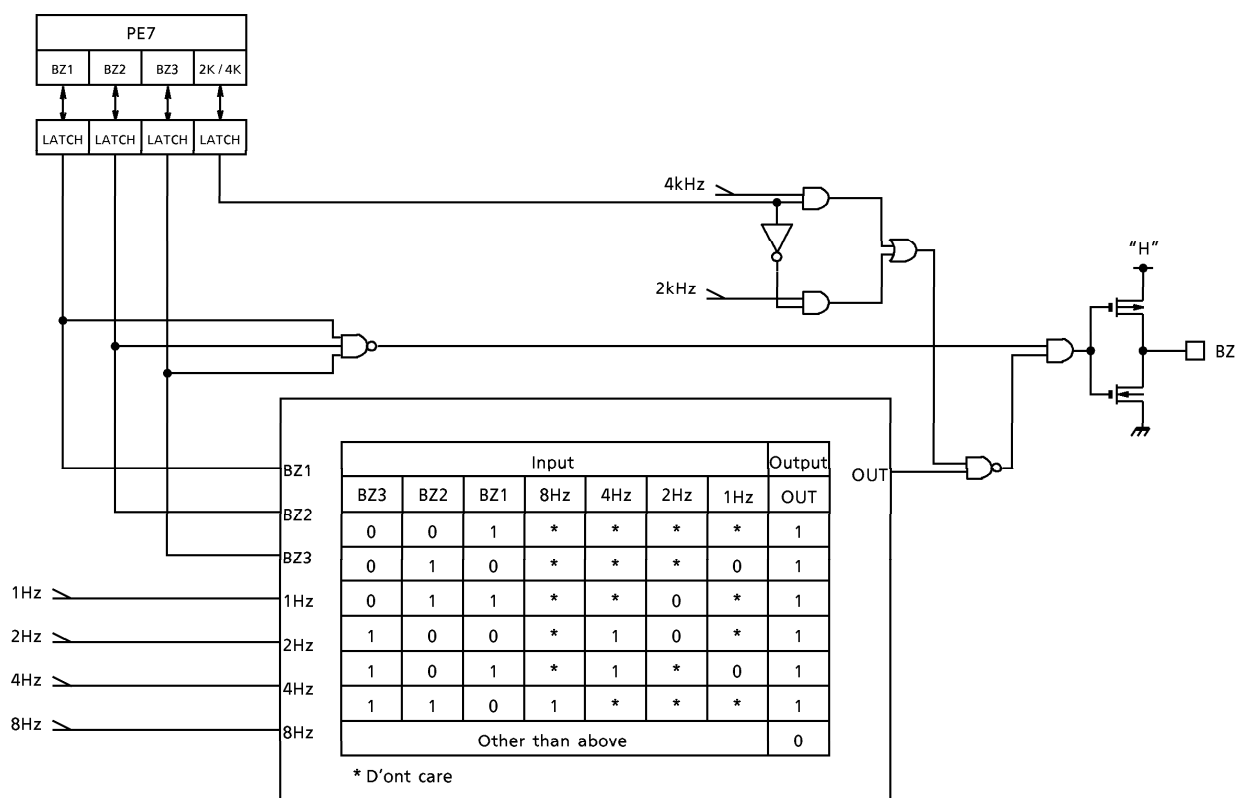


Fig.19 Buzzer Circuit

6. LCD Circuit

The LCD driver circuit has common signals and segment signals to drive 4.5V, 1/16 duty, 1/4 bias LCD.

Duty	Frame frequency	COMMON	SEGMENT
1/16	97.5Hz	COM1~COM16	S1~S52

The LCD driver circuit is controlled by Register file both DSTA and DON, and Display RAM is enable on DRCE = 1.

	MSB	3	2	1	0	LSB
PC6W		—	DRCE	DON	DSTA	

DON	DSTA	Behavior of LCD driver
0	0	The booster circuit (Quadrupler) is turned off and all common & segment is fixed to VSS level. LCD shows full off display.
1	1	The booster circuit (Quadrupler) is turned on and LCD driver is enabled to display the data on Display RAM.
other than above		The setting other than above can cause mal-function. Do not set.

DRCE = 0 : disable Display RAM
 = 1 : enable Display RAM

(CAUTION)

1. Display signals from segment and common are made by the clock which come from low-speed oscillation. Even though the high-speed oscillator may be operating no display is output unless the low-speed oscillator is operating.
2. Register file DON and DSTA are read to Display Driver circuit by the clock which is made by LOWCP.
 When the LOWCP is needed OFF it is needs max. 103ms after changing the data of DON and DSTA.

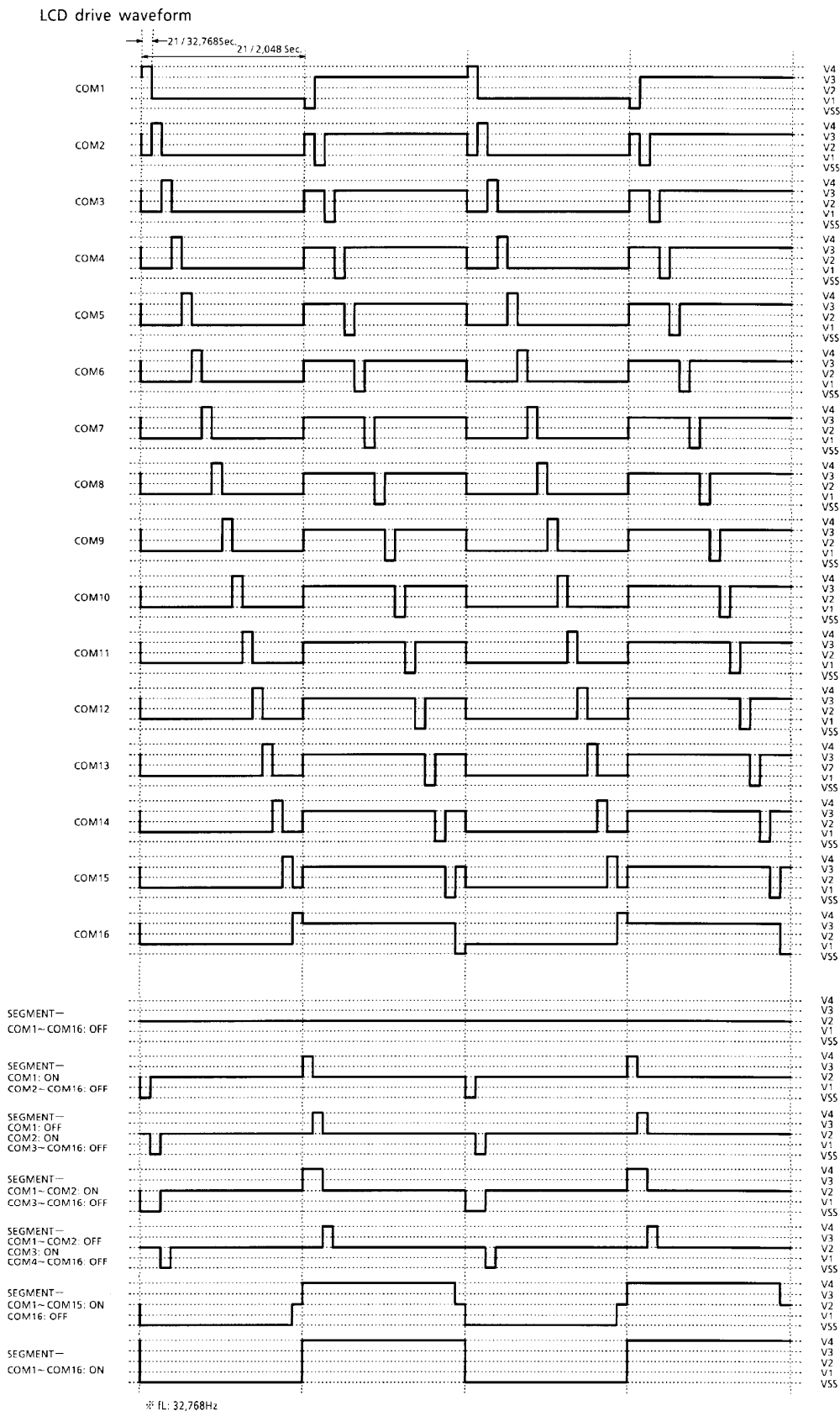


Fig.20 LCD drive waveform (1 / 16 duty)

7. Mask option

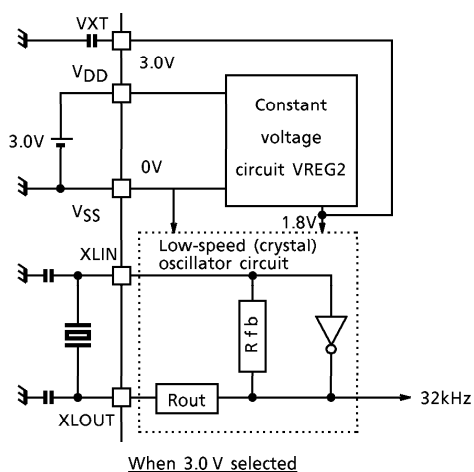
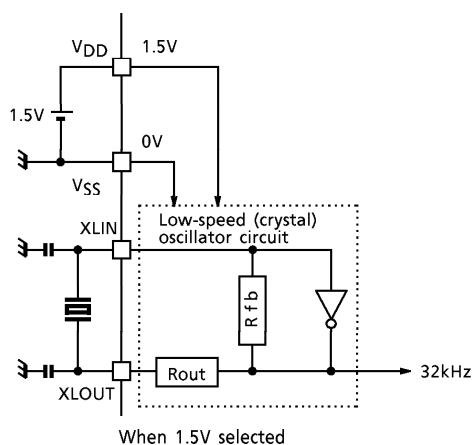
TMP04CH01FXXX has 10 Mask option.

Mask code	Battery	IN	I00	I01	I02	High-speed OSC	Low-speed OSC	Remark
A11F1	1.5V	IN (1)	I/O (1)	I/O (1)	I/O (2)	CR	X'tal	(*)
A11F3	1.5V	IN (1)	I/O (1)	I/O (1)	I/O (2)	CR	CR	(*)
A32F0	3.0V	IN (1)	I/O (2)	I/O (2)	I/O (2)	X'tal	X'tal	(*)
A32F1	3.0V	IN (1)	I/O (2)	I/O (2)	I/O (2)	CR	X'tal	(*)
A32F3	3.0V	IN (1)	I/O (2)	I/O (2)	I/O (2)	CR	CR	(*)
A33F0	3.0V	IN (1)	I/O (1)	I/O (1)	I/O (1)	X'tal	X'tal	(*)
A33F1	3.0V	IN (1)	I/O (1)	I/O (1)	I/O (1)	CR	X'tal	—
A33F3	3.0V	IN (1)	I/O (1)	I/O (1)	I/O (1)	CR	CR	(*)

(*) Under development

(1) Supply voltage

Either 1.5V or 3.0V can be selected as the supply voltage. When 3.0V is used, the low-speed oscillator circuit is driven by output from the internal constant voltage circuit (VREG2) thus reducing current dissipation.



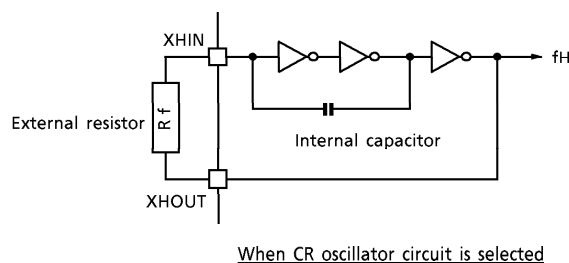
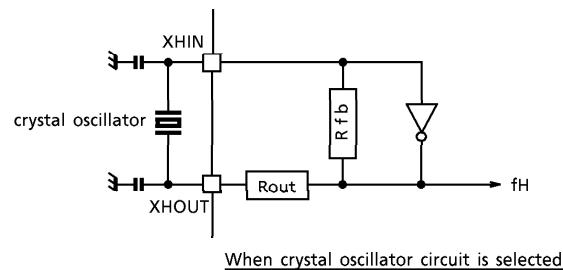
(2) Input/output port types

Either CMOS output or P-channel open drain can be selected in units of four bits for the input/output pins : IO01 to IO04, IO11 to IO14, IO21 to IO24. For port types, see the Diagram of Input / Output Port Types.

(3) High-speed oscillator circuit

Either the crystal or the CR oscillator circuit can be selected as the high-speed oscillator circuit.

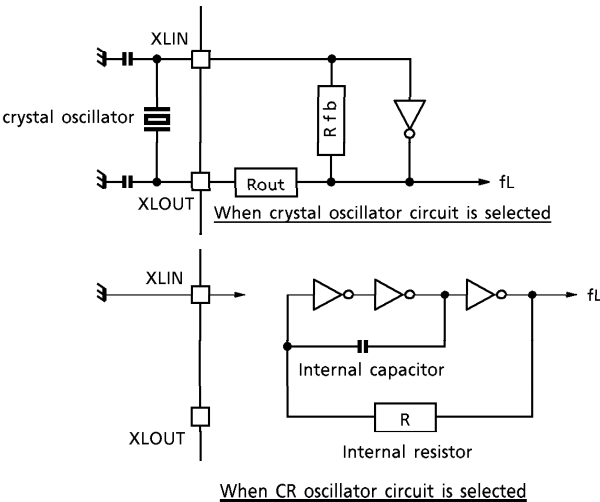
(Note) After a reset, the CPU starts operating using the high-speed clock as the system clock. Therefore, even if only a low-speed clock is used for the following processes, the high-speed oscillator circuit must operate normally at startup. Select either the crystal or the CR oscillator circuit and correctly connect the external component (crystal oscillator or resistor) to the XHIN/XHOUT pin.



(4) Low-speed oscillator circuit

Either the crystal or the CR oscillator circuit can be selected as the low-speed oscillator circuit.

(Note) A low-speed clock is used in the LCD driver circuit. To display the LCD, the low-speed oscillator circuit must be operated. When the CR oscillator circuit is selected, because both resistor and capacitor are built in, an external component is not required. Connect the XLIN pin to V_{SS} . If the pin is left open, the internal circuit gates become unstable, possibly allowing surge current to flow.



	Input / Output Circuit
IN (1)	
I / O (1)	
I / O (2)	

Fig.21 I / O port

RIN : Internal pull-down resistor, 400k Ω (Typ.)

R : Input protective resistor, 100 Ω (Typ.)

◆ELECTRICAL CHARACTERISTICS

1. Absolute maximum ratings ($V_{SS} = 0V$)

Characteristic	Symbol	Rating	Unit
Power Supply Voltage	V_{DD}	$-0.3 \sim 6.0$	V
Input Voltage	V_{IN}	$-0.3 \sim V_{DD} + 0.3$	V
Power Dissipation ($T_{Ope} = 80^{\circ}C$)	P_D	350	mW
Solder Temperature	T_{sol}	260 (10s)	$^{\circ}C$
Storage Temperature	T_{stg}	$-55 \sim 125$	$^{\circ}C$
Operating Temperature	T_{Ope}	$0 \sim 40$	$^{\circ}C$

2. 1.5V version (Unless otherwise specified, $V_{SS} = 0V$, $T_{Opr} = 0 \sim 40^{\circ}C$)

(Recommended operating condition)

Characteristic		Symbol	Test condition	Min	Typ.	Max	Unit
Power Supply Voltage		V _{DD}	f _{XTH} = 200kHz	1.2	1.5	1.8	V
Oscillation Frequency		f _{XTL1}	V _{DD} = 1.2~1.8V (Note 1)	—	32.768	—	kHz
		f _{XTL2}	V _{DD} = 1.5V (Note 2)	20	33	55	
		f _{XTH1}	V _{DD} = 1.5V (Note 3)	—	200	—	
Input Voltage	“H” Level	V _{IH}	V _{DD} = 1.3V	V _{DD} × 0.8	—	V _{DD}	V
			V _{DD} = 1.7V	V _{DD} × 0.7	—	V _{DD}	
	“L” Level	V _{IL}	V _{DD} = 1.3V	0	—	V _{DD} × 0.2	
			V _{DD} = 1.7V	0	—	V _{DD} × 0.3	
Quadrupler Capacitance		C ₁ , C ₂		—	1.0	—	μF
Voltage Capacitance		V ₁		—	1.0	—	μF
		V ₂		—	1.0	—	
		V ₃		—	1.0	—	
		V ₄		—	1.0	—	

(Note 1) Crystal oscillation circuit is used for low-speed oscillator.

(Note 2) Internal CR oscillator is used for low-speed oscillator.

(Note 3) An RC oscillating circuit configured with an external R is used for the high-speed oscillator.

Oscillation

Characteristic	Symbol	Test condition	Min	Typ.	Max	Unit
OSC Starting Voltage	V _{STA}	T _{STA} = 10S, T _{opr} = 25°C (Note 1)	1.4	—	—	V
OSC Holding Voltage	V _{HOLD}	(Note 1)	1.2	—	—	V
Frequency Of Internal CR OSC	F _{OSC1}	V _{DD} = 1.5V (Note 2)	20	33	55	kHz
Frequency of High-Speed OSC	F _{OSC2}	V _{DD} = 1.5V R _f = 150kΩ (Note 3)	—	200	—	kHz

(Note 1) Crystal oscillation circuit for low-speed oscillator.
Input 1.4V or more at power-on.

(Note 2) Internal CR oscillator for low-speed oscillator.

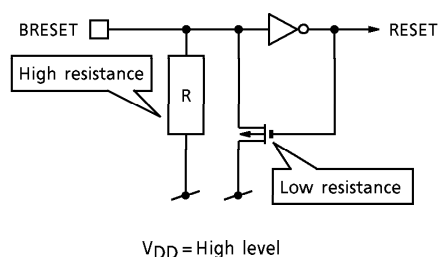
(Note 3) An RC oscillating circuit configured with an external R is used for the high-speed oscillator.

DC CHARACTERISTICS

Characteristic	Symbol	Test condition	Min	Typ.	Max	Unit
Input Current (1) (IN1~IN4, IO01~IO04, IO11~IO14)	I _{IH1}	V _{DD} = 1.8V, V _{IN} = 0V	- 500	—	500	nA
	I _{IL1}	V _{DD} = 1.8V, V _{IN} = 1.8V	3.21	4.5	7.5	μA
Input Current (1-2) (IO21~IO24)	I _{IH1}	V _{DD} = 1.8V, V _{IN} = 0V	- 500	—	500	nA
	I _{IL1}	V _{DD} = 1.8V, V _{IN} = 1.8V	- 500	—	500	
Input Current (2) (BRESET)	I _{IH2L} (Note)	V _{DD} = 1.8V, V _{IN} = 0V Low Register side	- 60	- 36	- 25.7	μA
	I _{IH2H}	V _{DD} = 1.8V, V _{IN} = 0V High Register side	- 6	- 3.6	- 2.57	
Input Current (3) (TEST)	I _{IL3}	V _{DD} = 1.8V, V _{IN} = 1.8V	6.43	9.0	15.0	μA
Output Current (1) (IO01~IO04, IO11~IO14)	I _{OH1}	V _{DD} = 1.2V, V _{OH} = 0.7V	—	—	- 150	μA
	I _{OL1}	V _{DD} = 1.2V, V _{OL} = 0.5V	0.89	1.25	2.08	
Output Current (1-2) (IO21~IO24)	I _{OH1}	V _{DD} = 1.2V, V _{OH} = 0.7V	—	—	- 150	μA
Output Current (2) (BZ)	I _{OH2}	V _{DD} = 1.2V, V _{OH} = 0.7V	—	—	- 500	μA
	I _{OL2}	V _{DD} = 1.2V, V _{OL} = 0.5V	500	—	—	
Output Current (3) (SEGMENT)	I _{OH3}	V ₁ = 1.125V, V ₂ = 2.25V, V ₃ = 3.375V, V ₄ = 4.5V	V _{OH} = V ₄ - 0.5V		- 100	μA
	I _{OL3}		V _{OL} = 0.5V		100	
	I _{OM3}		V _{OM} = V ₂ - 0.5V		- 50	

Characteristic	Symbol	Test condition		Min	Typ.	Max	Unit
Output Current (4) (COMMON)	I _{OH4}	V ₁ = 1.125V,	V _{OH} = V ₄ - 0.5V	—	—	- 100	μ A
	I _{OL4}	V ₂ = 2.25V,	V _{OL} = 0.5V	100	—	—	
	I _{OM4}	V ₃ = 3.375V,	V _{OM} = V ₃ - 0.5V	—	—	- 50	
	I _{OM4}	V ₄ = 4.5V	V _{OM} = V ₁ + 0.5V	50	—	—	
Quadrupler Output	V ₁	V ₁ = 1.125V, Ta = 25°C		1.075	1.125	1.175	V
	V ₂			2.05	2.25	2.45	
	V ₃			3.175	3.375	3.575	
	V ₄			4.3	4.5	4.7	
Power Supply Current (1) (Low-Speed Crystel) (Oscillation Circuit)	I _{DDOP}	V _{DD} = 1.5V, f _H = 200kHz f _L = 32kHz At high-speed operation	Display ON	—	48	77	μ A
			Display OFF	—	—	73	
	I _{DDSLow}	V _{DD} = 1.5V, f _L = 32kHz At low-speed operation	Display ON	—	9.5	12	
			Display OFF	—	—	11	
	I _{DDHOLD}	V _{DD} = 1.5V, f _L = 32kHz In HOLD mode	Display ON	—	4	7	
			Display OFF	—	—	6	
Power Supply Current (2) (Low-Speed CR) (Oscillation Circuit)	I _{DDOP}	V _{DD} = 1.5V, f = 200kHz f _L = Internal At high-speed operation	Display ON	—	50	77	μ A
			Display OFF	—	—	73	
	I _{DDSLow}	V _{DD} = 1.5V, f _L = Internal At low-speed operation	Display ON	—	12	17	
			Display OFF	—	—	16	
	I _{DDHOLD}	V _{DD} = 1.5V, f _L = Internal In HOLD mode	Display ON	—	5	7.5	
			Display OFF	—	—	6.5	
Power Supply Current (2) (Low-Speed CR) (Oscillation Circuit)	I _{DDSTOP}	V _{DD} = 1.5V In STOP mode		—	0.4	1	

(Note) The BRESET pin is connected to V_{DD} (High level) via two resistors as shown below. To minimize the current that flows at reset, the low resistance consists of a P-channel FET. When the input level is V_{SS} (Low level), the FET is off. The resistance is ∞ . The specified input current (2), I_{IH2L}, is the current that flows when the low resistance = P-channel FET is on. However, the low-resistance is off when V_{IN} = 0V, so actual measurement is impossible.



3. 3.0V version ($V_{SS} = 0V$, $T_{opr} = 0 \sim 40^{\circ}C$)

(Typical operating condition)

Characteristic		Symbol	Test condition	Min	Typ.	Max	Unit
Power Supply Voltage		V _{DD}	f _{XTH} = 2MHz	2.4	3.0	3.6	V
Oscillation Frequency		f _{XTL1}	V _{DD} = 2.4~3.6V (Note 1)	—	32.768	—	kHz
		f _{XTL2}	V _{DD} = 3.0V (Note 2)	20	35	60	
		f _{XTH1}	V _{DD} = 2.4~3.6V (Note 3)	—	2.0	—	MHz
		f _{XTH2}	V _{DD} = 3.0V (Note 4)	—	2.0	—	
Input Voltage	“H” Level	V _{IH}	V _{DD} = 2.4V	V _{DD} × 0.8	—	V _{DD}	V
			V _{DD} = 3.6V	V _{DD} × 0.7	—	V _{DD}	
	“L” Level	V _{IL}	V _{DD} = 2.4V	0	—	V _{DD} × 0.2	
			V _{DD} = 3.6V	0	—	V _{DD} × 0.3	
Quadrupler Capacitance		C ₁ , C ₂		—	1.0	—	μF
Voltage Capacitance		V ₂		—	1.0	—	μF
		V ₃		—	1.0	—	
		V ₄		—	1.0	—	
		V _{XT}		—	1.0	—	

(Note 1) Crystal oscillation circuit is used for low-speed oscillator.

(Note 2) Internal CR oscillator is used for low-speed oscillator.

(Note 3) Crystal oscillation circuit is used for high-speed oscillator.

(Note 4) An RC oscillating circuit configured with an external R is used for the high-speed oscillator.

Oscillation

Characteristic	Symbol	Test condition	Min	Typ.	Max	Unit
OSC Starting Voltage (Low speed)	V_{STA1}	$T_{STA} = 10s$, $T_{opr} = 25^{\circ}C$	1.85	—	—	V
OSC Starting Voltage (High speed)	V_{STA2}	$T_{STA} = 8ms$	2.10	—	—	V
OSC Holding Voltage (Low speed)	V_{HOLD1}		1.65	—	—	V
OSC Holding Voltage (High speed)	V_{HOLD2}		1.90	—	—	V
Frequency Of Internal CR OSC	f_{OSC1}	$V_{DD} = 3.0V$ (Note 1)	20	35	60	kHz
Frequency Of High-Speed OSC	f_{OSC2}	$V_{DD} = 3.0V$ $R_f = 13.0k\Omega$ (Note 2)	—	2.0	—	MHz

(Note 1) Internal CR oscillator for low-speed oscillator.

(Note 2) An RC oscillating circuit configured with an external R is used for the high-speed oscillator.

DC CHARACTERISTICS

Characteristic	Symbol	Test condition		Min	Typ.	Max	Unit
Input Current (1-1) (IN1~IN4)	I _{IH1}	V _{DD} = 3.6V, V _{IN} = 0V		- 500	—	500	nA
	I _{IL1}	V _{DD} = 3.6V, V _{IN} = 3.6V		6.43	9.0	15.0	μA
Input Current (1-2) (IO01~IO04, IO11~IO14, IO21~IO24) (*1)	I _{IH1}	V _{DD} = 3.6V, V _{IN} = 0V		- 500	—	500	nA
	I _{IL1}	V _{DD} = 3.6V, V _{IN} = 3.6V		6.43	9.0	15.0	μA
Input Current (1-3) (IO01~IO04, IO11~IO14, IO21~IO24) (*2)	I _{IH1}	V _{DD} = 3.6V, V _{IN} = 0V		- 500	—	500	nA
	I _{IL1}	V _{DD} = 3.6V, V _{IN} = 3.6V		- 500	—	500	nA
Input Current (2) (BRESET)	I _{IH2L}	V _{DD} = 3.6V, V _{IN} = 0V Low Register side		- 120	- 72	- 51.4	μA
	I _{IH2H}	V _{DD} = 3.6V, V _{IN} = 0V High Register side		- 12	- 7.2	- 5.14	
Input Current (3) (TEST)	I _{IL3}	V _{DD} = 3.6V, V _{IN} = 3.6V		12.9	18.0	30.0	μA
Output Current (1) (IO01~IO04, IO11~IO14, IO21~IO24)	I _{OH1}	V _{DD} = 2.4V, V _{OH} = 1.9V		—	—	- 1.5	mA
	I _{OL1} (*1)	V _{DD} = 2.4V, V _{OH} = 0.5V		0.89	1.25	2.08	μA
Output Current (2) (BZ)	I _{OH2}	V _{DD} = 2.4V, V _{OH} = 1.9V		—	—	- 2.0	mA
	I _{OL2}	V _{DD} = 2.4V, V _{OL} = 0.5V		2.0	—	—	
Output Current (3) (SEGMENT)	I _{OH3}	V _{DD} = 3.0V, V _{REG} = 1.125V, V ₂ = 2.25V, V ₃ = 3.375V, V ₄ = 4.5V	V _{OH} = V ₄ - 0.5V	—	—	- 100	μA
	I _{OL3}		V _{OL} = 0.5V	100	—	—	
	I _{OM3}		V _{OM} = V ₂ - 0.5V	—	—	- 50	
Output Current (4) (COMMON)	I _{OH4}	V _{DD} = 3.0V, V _{REG} = 1.125V, V ₂ = 2.25V, V ₃ = 3.375V, V ₄ = 4.5V	V _{OH} = V ₄ - 0.5V	—	—	- 100	μA
	I _{OL4}		V _{OL} = 0.5V	100	—	—	
	I _{OM4}		V _{OM} = V ₃ - 0.5V	—	—	- 50	
	I _{OM4}		V _{OM} = V ₁ + 0.5V	50	—	—	
Voltage Regulator Output	V _{REG1}	V _{DD} = 3.0V, Ta = 25°C (*3)		1.075	1.125	1.175	V
	V _{REG2}	V _{DD} = 3.0V, Ta = 25°C (*4)		—	1.8	—	
Quadrupler Output	V ₂	V _{DD} = 3.0V V _{REG} = 1.125V, Ta = 25°C		2.05	2.25	2.45	V
	V ₃			3.175	3.375	3.575	
	V ₄			4.3	4.5	4.7	

(*1) MASK CODE : A33F0, A33F1, A33F3

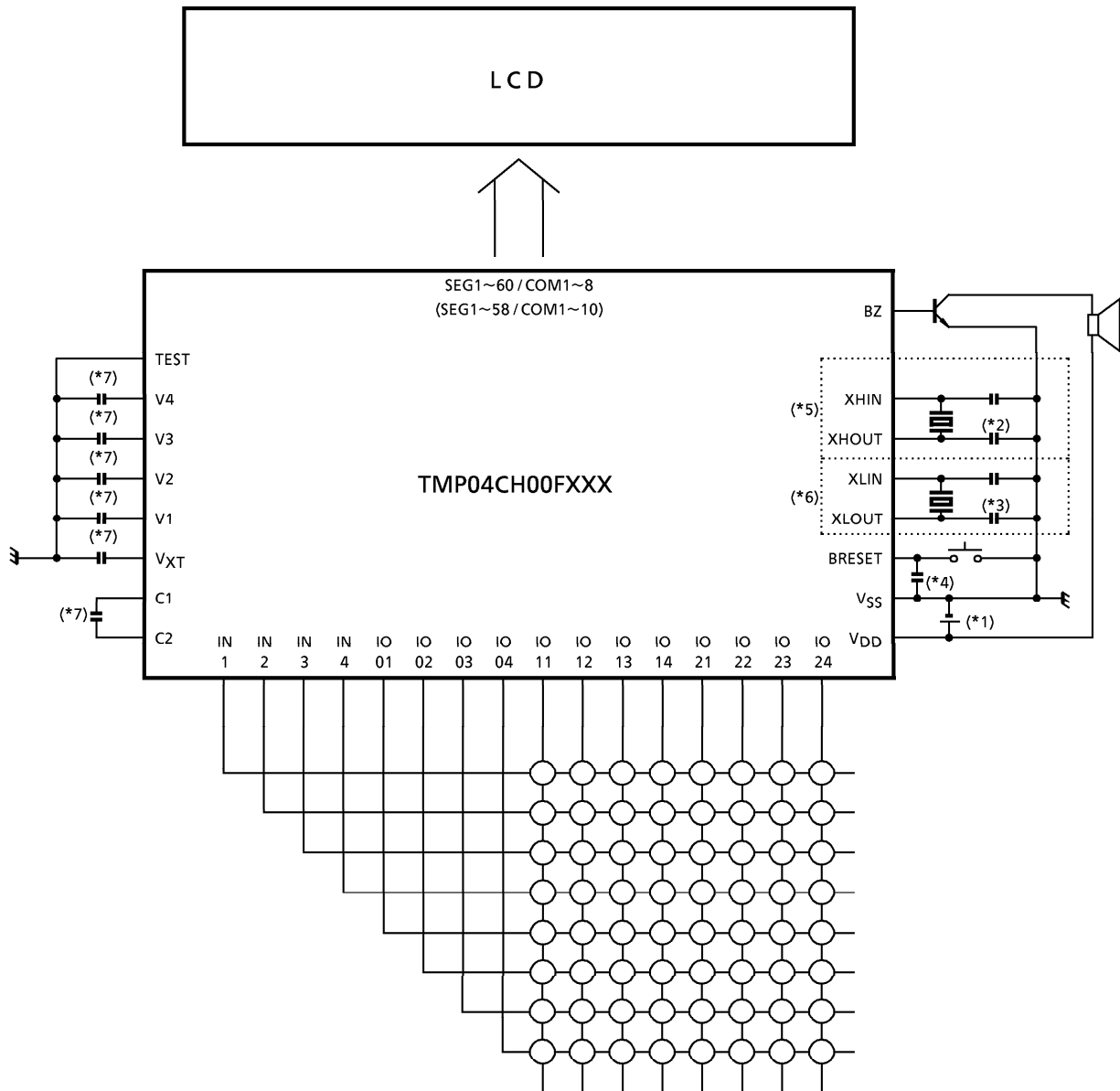
(*2) MASK CODE : A32F0, A32F1, A32F3

(*3) Voltage regulator for quadrupler

(*4) Voltage output regulator for low-speed oscillator

Characteristic	Symbol	Test condition		Min	Typ.	Max	Unit
Power Supply Current (1) (High-Speed Crystal Oscillation Circuit) (Low-Speed Crystal Oscillation Circuit)	I _{DDOP}	V _{DD} = 3.0V, f _H = 2MHz f _L = 32kHz At high-speed operation	Display ON	—	0.85	1.2	mA
			Display OFF	—	—	1.2	
	I _{DDSLow}	V _{DD} = 3.0V, f _L = 32kHz At low-speed operation	Display ON	—	17.0	24.0	μA
			Display OFF	—	—	23.0	
	I _{DDHOLD}	V _{DD} = 3.0V, f _L = 32kHz In HOLD mode	Display ON	—	5.5	11.0	
			Display OFF	—	—	10.0	
	I _{DDSTOP}	V _{DD} = 3.0V In STOP mode		—	0.8	1.2	
Power Supply Current (2) (High-Speed CR Oscillation Circuit) (Low-Speed Crystal Oscillation Circuit)	I _{DDOP}	V _{DD} = 3.0V, f _H = 2MHz f _L = 32kHz At high-speed operation	Display ON	—	0.85	1.5	mA
			Display OFF	—	—	1.5	
	I _{DDSLow}	V _{DD} = 3.0V, f _L = 32kHz At low-speed operation	Display ON	—	17.0	24.0	μA
			Display OFF	—	—	23.0	
	I _{DDHOLD}	V _{DD} = 3.0V, f _L = 32kHz In HOLD mode	Display ON	—	5.5	11.0	
			Display OFF	—	—	10.0	
	I _{DDSTOP}	V _{DD} = 3.0V In STOP mode		—	0.8	1.2	
Power Supply Current (3) (High-Speed CR Oscillation Circuit) (Low-Speed CR Oscillation Circuit)	I _{DDOP}	V _{DD} = 3.0V, f _H = 2MHz f _L = Internal At high-speed operation	Display ON	—	0.85	1.5	mA
			Display OFF	—	—	1.5	
	I _{DDSLow}	V _{DD} = 3.0V, f _L = Internal At low-speed operation	Display ON	—	23.0	40.0	μA
			Display OFF	—	—	39.0	
	I _{DDHOLD}	V _{DD} = 3.0V, f _L = Internal In HOLD mode	Display ON	—	6.5	14.0	
			Display OFF	—	—	12.0	
	I _{DDSTOP}	V _{DD} = 3.0V In STOP mode		—	0.8	1.4	

◆EXAMPLE OF APPLICATION CIRCUIT



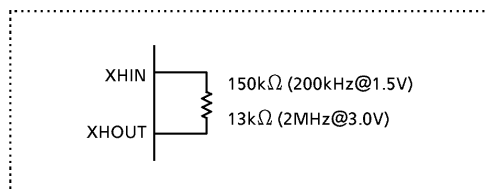
(*1) Either 1.5V or 3V can be selected as the supply voltage.

(*2) Recommended high-speed oscillator circuit capacitor: 22pF

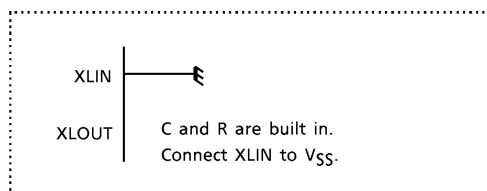
(*3) Recommended low-speed oscillator circuit capacitor : 15pF

(*4) Insert a 0.1 μ F capacitor between BRESET and VSS.

(*5) High-speed CR oscillator circuit (optional)



(*6) Low-speed CR oscillator circuit (optional)

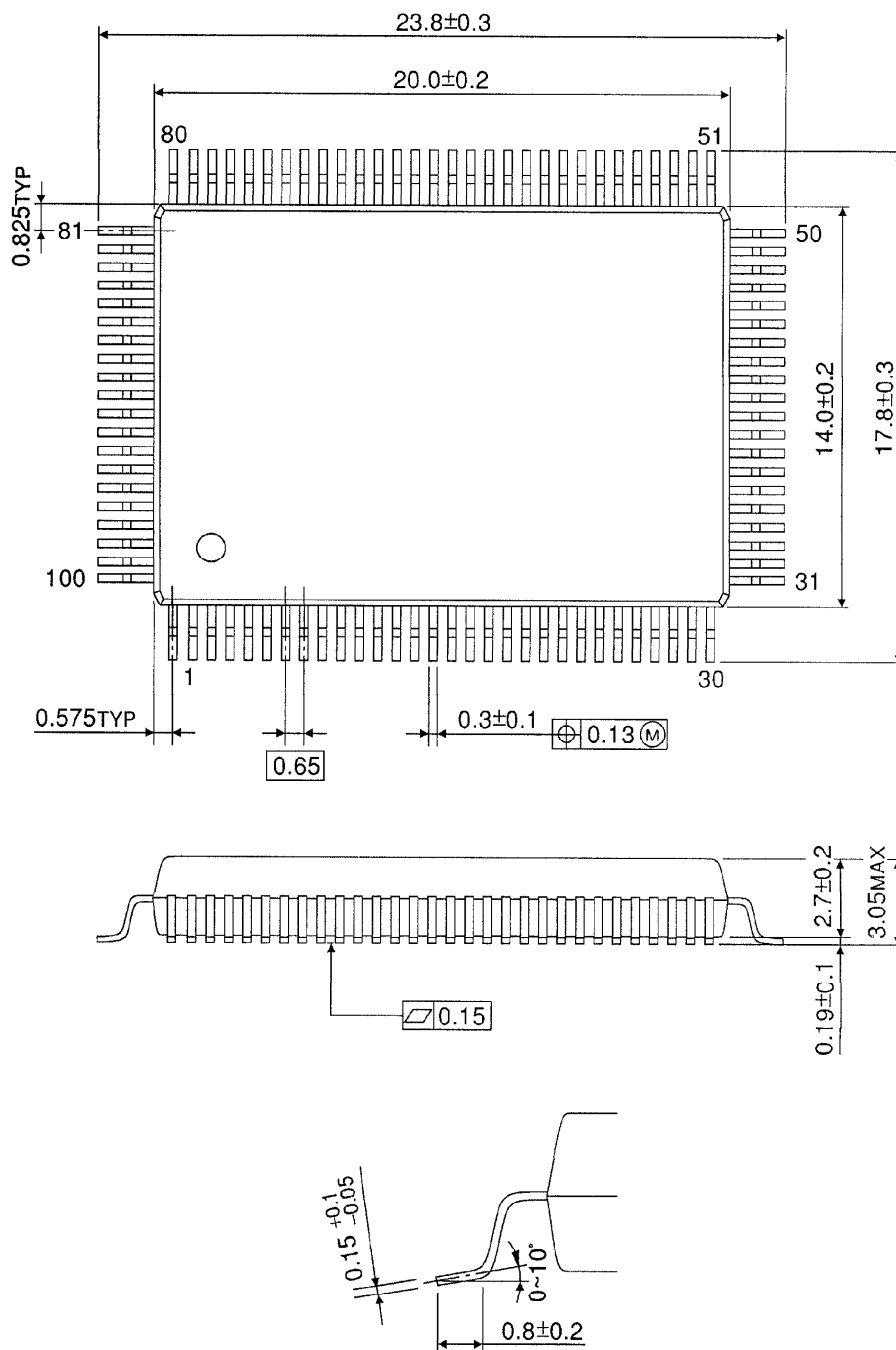


(*7) Adjust between 0.1 to 1.0μF depending on the size of the LCD panel used.

◆ **PACKAGING**

(1) P-QFP100-1420-0.65A

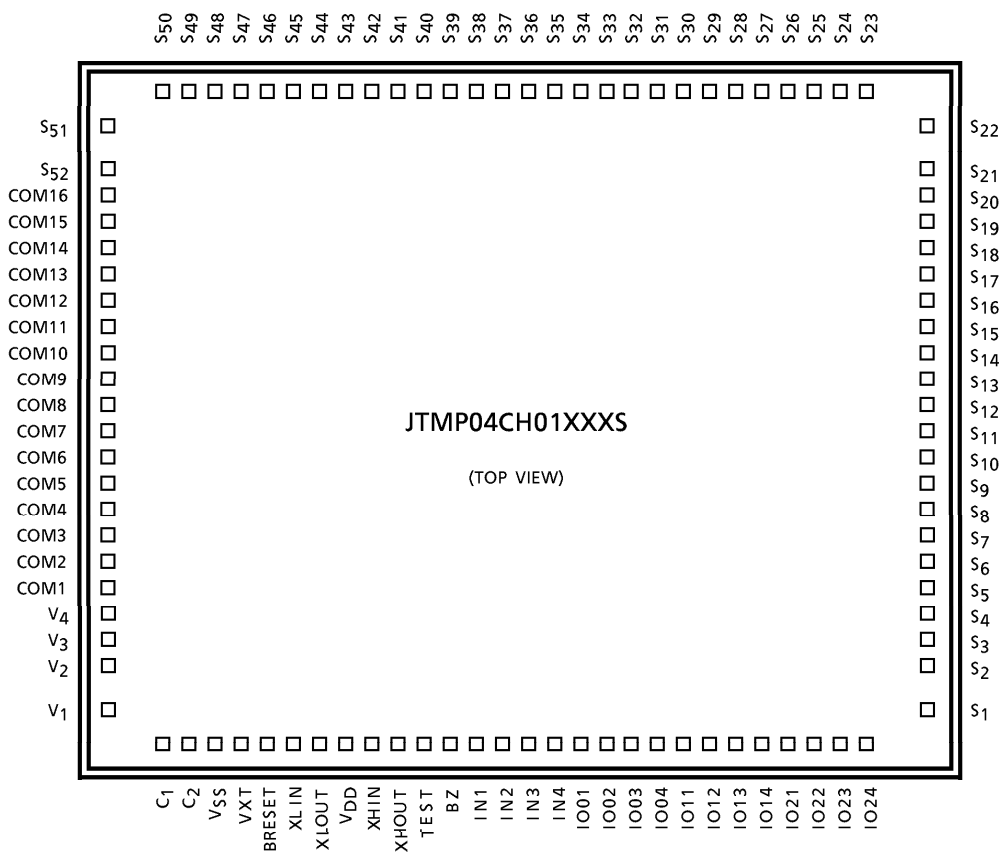
Unit : mm



Weight : 1.65g (Typ.)

(2) Bare Chip

1. Pad assignment



Chip size 5.04 x 5.78 (mm)

Chip thickness 450 ± 30 (μm)

Substrate voltage VSS

2. Pad location table

(× 10⁻³mm)

No.	PAD NAME	X POINT	Y POINT
1	V ₁	- 1957	2653
2	C ₁	- 2253	2375
3	C ₂	- 2253	2201
4	V _{SS}	- 2253	2038
5	VXT	- 2253	1871
6	BRESET	- 2253	1699
7	XLIN	- 2253	1519
8	XLOUT	- 2253	1345
9	V _{DD}	- 2253	1144
10	XHIN	- 2253	944
11	XHOUT	- 2253	772
12	TEST	- 2253	592
13	BZ	- 2253	410
14	IN1	- 2253	227
15	IN2	- 2253	59
16	IN3	- 2253	- 112
17	IN4	- 2253	- 280
18	IO01	- 2253	- 468
19	IO02	- 2253	- 639
20	IO03	- 2253	- 815
21	IO04	- 2253	- 986
22	IO11	- 2253	- 1162
23	IO12	- 2253	- 1333
24	IO13	- 2253	- 1509
25	IO14	- 2253	- 1680
26	IO21	- 2253	- 1856
27	IO22	- 2253	- 2027
28	IO23	- 2253	- 2203
29	IO24	- 2253	- 2374
30	S ₁	- 1960	- 2653
31	S ₂	- 1628	- 2653
32	S ₃	- 1460	- 2653
33	S ₄	- 1285	- 2653
34	S ₅	- 1117	- 2653
35	S ₆	- 942	- 2653
36	S ₇	- 774	- 2653

No.	PAD NAME	X POINT	Y POINT
37	S ₈	- 599	- 2653
38	S ₉	- 431	- 2653
39	S ₁₀	- 256	- 2653
40	S ₁₁	- 85	- 2653
41	S ₁₂	85	- 2653
42	S ₁₃	258	- 2653
43	S ₁₄	428	- 2653
44	S ₁₅	601	- 2653
45	S ₁₆	771	- 2653
46	S ₁₇	944	- 2653
47	S ₁₈	1114	- 2653
48	S ₁₉	1287	- 2653
49	S ₂₀	1457	- 2653
50	S ₂₁	1630	- 2653
51	S ₂₂	1959	- 2653
52	S ₂₃	2253	- 2283
53	S ₂₄	2253	- 2112
54	S ₂₅	2253	- 1945
55	S ₂₆	2253	- 1774
56	S ₂₇	2253	- 1607
57	S ₂₈	2253	- 1436
58	S ₂₉	2253	- 1269
59	S ₃₀	2253	- 1098
60	S ₃₁	2253	- 931
61	S ₃₂	2253	- 760
62	S ₃₃	2253	- 593
63	S ₃₄	2253	- 422
64	S ₃₅	2253	- 255
65	S ₃₆	2253	- 84
66	S ₃₇	2253	84
67	S ₃₈	2253	255
68	S ₃₉	2253	422
69	S ₄₀	2253	593
70	S ₄₁	2253	760
71	S ₄₂	2253	931
72	S ₄₃	2253	1098

No.	PAD NAME	X POINT	Y POINT
73	S ₄₄	2253	1269
74	S ₄₅	2253	1436
75	S ₄₆	2253	1607
76	S ₄₇	2253	1774
77	S ₄₈	2253	1945
78	S ₄₉	2253	2112
79	S ₅₀	2253	2283
80	S ₅₁	1959	2653
81	S ₅₂	1629	2653
82	COM16	1459	2653
83	COM15	1286	2653
84	COM14	1116	2653
85	COM13	943	2653
86	COM12	773	2653
87	COM11	600	2653
88	COM10	430	2653
89	COM9	257	2653
90	COM8	87	2653
91	COM7	- 87	2653
92	COM6	- 257	2653
93	COM5	- 430	2653
94	COM4	- 600	2653
95	COM3	- 773	2653
96	COM2	- 943	2653
97	COM1	- 1116	2653
98	V ₄	- 1291	2653
99	V ₃	- 1468	2653
100	V ₂	- 1638	2653